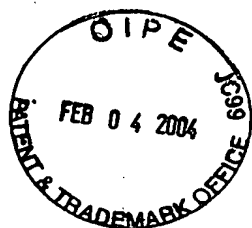


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Publication	PECVD Reaction	'DELTA-n' Control Method	Post-dep. Themat Treatment T° (°C)
Valette S., 1987	Unknown	P doping	Not specified
Valette S., 1988	Unknown	P doping	400°C
Grand G., 1990	Unknown	P doping	1000°C
Lui K., 1995	Unknown	Content in Si, P	Not specified
Ojha S., 1998	Unknown	Ge, B, or P doping	Not specified
Canning J., 1998	Unknown	Ge doping	Not specified
Bulla D., 1998	TEOS	TEOS	Not specified
Johnson C., 1998	SiH₄ + O₂	Si ion Implantation	400°C
Boswell R. W., 1997	SiH ₄ + O ₂	SiH ₄ /O ₂ flow ratio	1000°C
Bazylenko M. V., 1995	SiH ₄ + O ₂ + CF ₄	(SiH ₄ +O ₂)/CF ₄ flow ratio	Not specified
Bazylenko M. V., 1996	SiH ₄ + O ₂ + CF ₄	(SiH ₄ +O ₂)/CF ₄ flow ratio	1000°C
Durandet A., 1996	SiH₄ + O₂ + CF₄	(SiH₄+O₂)/CF₄ flow ratio	100°C
Kasper K., 1991	SiH ₄ + N ₂ O	SiH ₄ /N ₂ O flow ratio	1060°C
Lai Q., 1992	SiH ₄ + N ₂ O	SiH ₄ /N ₂ O flow ratio	1100°C
Lai Q., 1993	SiH ₄ + N ₂ O	SiH ₄ /N ₂ O flow ratio	1100°C
Pereyra I., 1997	SiH₄ + N₂O	SiH₄/N₂O flow ratio	400°C
Alayo M., 1998	SiH ₄ + N ₂ O	SiH ₄ /N ₂ O flow ratio	1000°C
Kenyon T., 1997	SiH ₄ + N ₂ O + Ar	SiH ₄ /N ₂ O/Ar flow ratio	1000°C
Lam D. K. W., 1984	SiH ₄ + N ₂ O + NH ₃	SiH ₄ /N ₂ O/NH ₃ flow ratio	Not specified
Bruno F., 1991	SiH ₄ + N ₂ O + NH ₃	SiH ₄ /N ₂ O/NH ₃ flow ratio	1100°C
Yokohama S., 1995	SiH ₄ + N ₂ O + NH ₃	SiH ₄ /N ₂ O/NH ₃ flow ratio	Not specified
Agnihotri O. P., 1997	SiH₄ + N₂O + NH₃	SiH₄/N₂O/NH₃ flow ratio	700-900°C
Germann R., 1999	SiH ₄ + N ₂ O + NH ₃	Unknown	1100°C
Offrein B., 1999	SiH ₄ + N ₂ O + NH ₃	Unknown	1150°C
Hoffmann M., 1995	SiH ₄ + N ₂ O + NH ₃ + Ar	SiH ₄ /N ₂ O/NH ₃ /Ar flow ratio	Not specified
Hoffmann M., 1997	SiH ₄ + N ₂ O + NH ₃ + Ar	SiH ₄ /N ₂ O/NH ₃ /Ar flow ratio	Not specified
Tu Y., 1995	SiH ₄ + N ₂ O + NH ₃ + N ₂	N ₂ O/(N ₂ O + NH ₃) flow ratio	1050°C
Poenar D., 1997	SiH ₄ + N ₂ O + NH ₃ + N ₂	SiH ₄ /N ₂ O/NH ₃ /N ₂ flow ratio	850°C
Ridder R., 1998	SiH ₄ + N ₂ O + NH ₃ + N ₂	SiH ₄ /N ₂ O/NH ₃ /Ar flow ratio	1100°C
Worhoff., K 1999	SiH ₄ + N ₂ O + NH ₃ + N ₂	SiH ₄ /N ₂ O/NH ₃ /N ₂ flow ratio	1150°C
Bulat E.S., 1993	SiH₄ + N₂O + N₂ + O₂ + He + CF₄	SiH₄/(N₂O/N₂)/O₂/CF₄ flow ratio	425°C
This Patent Application	SiH₄ + N₂O + PH₃ + N₂	Patented Pending Method	650°C

FIG. 1



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	H-O-H	Si-O-H	Si-N-H	Si-N-H	Si-H	Si=O	N=N	Si-O-Si	Si-O-Si	Si-ON	Si-OH	Si-O-Si	Si-O-Si
Min	3550	3470	3380	3300	2210	1800	1530	1080	1000	910	860	740	410
Ave	3650	3510	3420	3380	2260	1875	1555	1180	1080	950	885	810	460
Max	3750	3550	3460	3460	2310	1950	1580	1280	1160	990	910	880	510
Min	2.817	2.882	2.959	3.030	4.525	5.556	6.536	9.259	10.000	10.989	11.628	13.514	24.390
Ave	2.740	2.849	2.924	2.959	4.425	5.333	6.431	8.475	9.256	10.526	11.299	12.346	21.739
Max	2.667	2.817	2.890	2.890	4.329	5.128	6.329	7.813	8.621	10.101	10.989	11.364	19.608
Min	1.408	1.441	1.479	1.515	2.262	2.778	3.268	4.630	5.000	5.495	5.814	6.757	12.195
Ave	1.370	1.425	1.462	1.479	2.212	2.667	3.215	4.237	4.630	5.263	5.650	6.173	10.870
Max	1.333	1.408	1.445	1.445	2.165	2.564	3.165	3.906	4.310	5.051	5.495	5.682	9.804
Min	0.939	0.961	0.986	1.010	1.508	1.852	2.179	3.086	3.333	3.663	3.876	4.505	8.130
Ave	0.913	0.950	0.975	0.986	1.475	1.778	2.144	2.825	3.086	3.509	3.766	4.115	7.246
Max	0.889	0.939	0.963	0.963	1.443	1.709	2.110	2.604	2.874	3.367	3.663	3.788	6.536
Min	0.704	0.720	0.740	0.758	1.131	1.389	1.634	2.315	2.500	2.747	2.907	3.378	6.098
Ave	0.685	0.712	0.731	0.740	1.106	1.333	1.608	2.119	2.315	2.632	2.825	3.086	5.435
Max	0.667	0.704	0.723	0.723	1.082	1.282	1.582	1.953	2.155	2.525	2.747	2.841	4.902
Min	0.563	0.576	0.592	0.606	0.905	1.111	1.307	1.852	2.000	2.198	2.326	2.703	4.878
Ave	0.548	0.570	0.585	0.592	0.885	1.067	1.286	1.695	1.852	2.105	2.260	2.469	4.348
Max	0.533	0.563	0.578	0.578	0.866	1.026	1.266	1.563	1.724	2.020	2.198	2.273	3.922
Min	0.469	0.480	0.493	0.505	0.754	0.926	1.089	1.543	1.667	1.832	1.938	2.252	4.065
Ave	0.457	0.475	0.487	0.493	0.737	0.889	1.072	1.412	1.543	1.754	1.883	2.058	3.623
Max	0.444	0.469	0.482	0.482	0.722	0.855	1.055	1.302	1.437	1.684	1.832	1.894	3.268
Min	0.402	0.412	0.423	0.433	0.646	0.794	0.934	1.323	1.429	1.570	1.661	1.931	3.484
Ave	0.391	0.407	0.418	0.423	0.632	0.762	0.919	1.211	1.323	1.504	1.614	1.764	3.106
Max	0.381	0.402	0.413	0.413	0.618	0.733	0.904	1.116	1.232	1.443	1.570	1.623	2.801
Min	0.352	0.360	0.370	0.379	0.566	0.694	0.817	1.157	1.250	1.374	1.453	1.689	3.049
Ave	0.342	0.356	0.365	0.370	0.553	0.667	0.804	1.059	1.157	1.316	1.412	1.543	2.717
Max	0.333	0.352	0.361	0.361	0.541	0.641	0.791	0.977	1.078	1.263	1.374	1.420	2.451

FIG. 2



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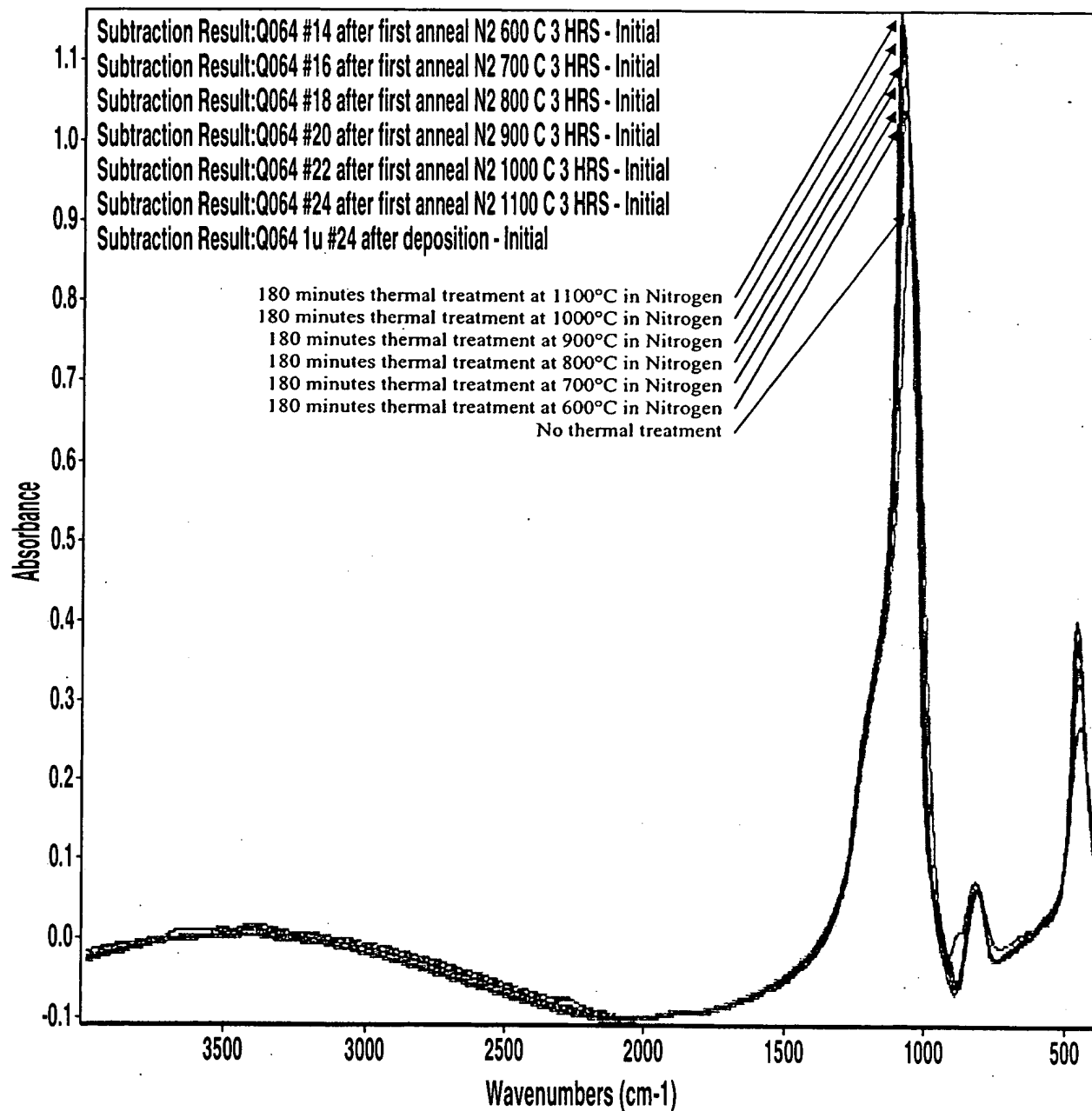


FIG. 3a



SIN 09/956,916
A/U 1762

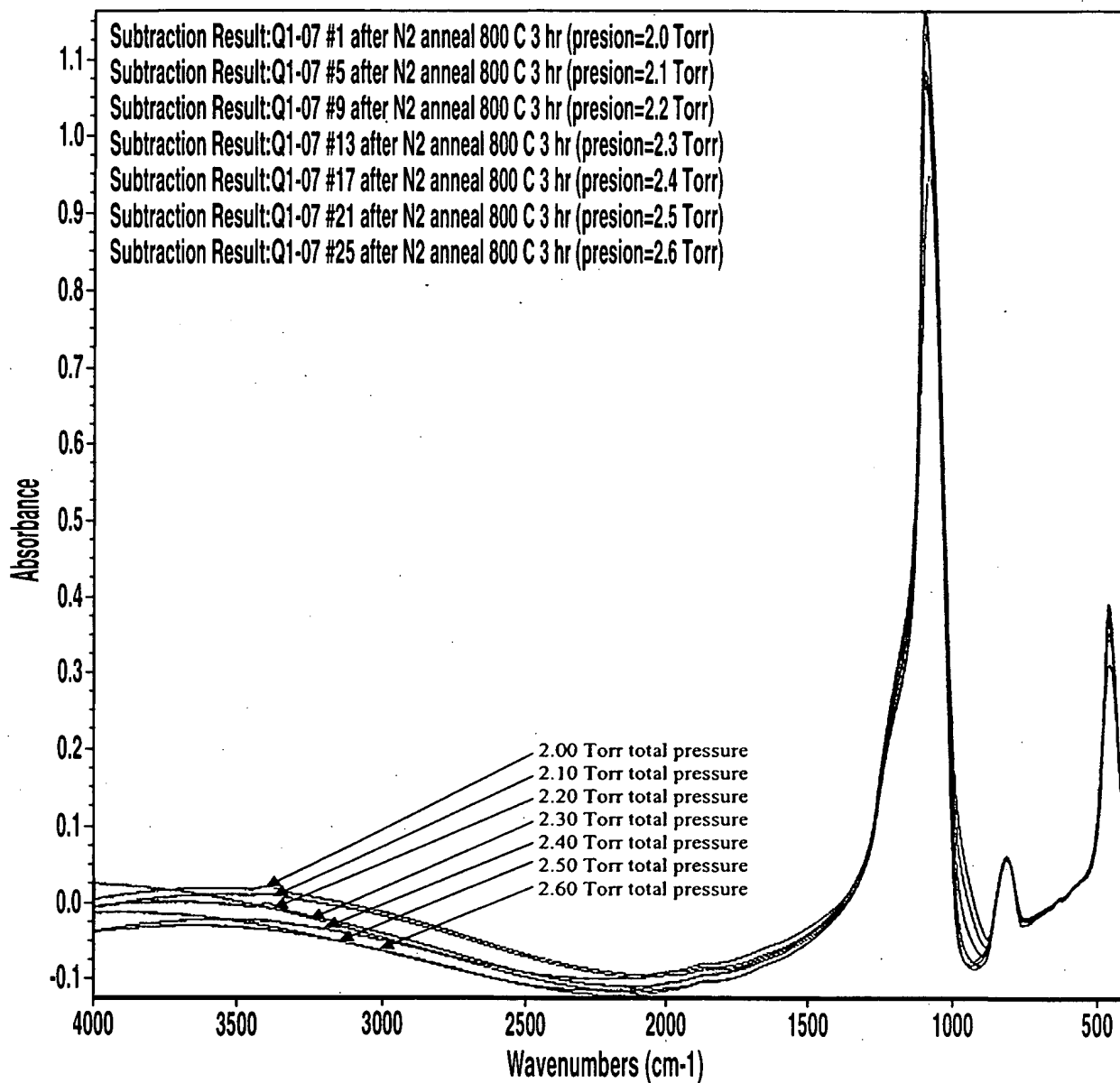


FIG. 3b



S/N 09/956,916
A1U 1762

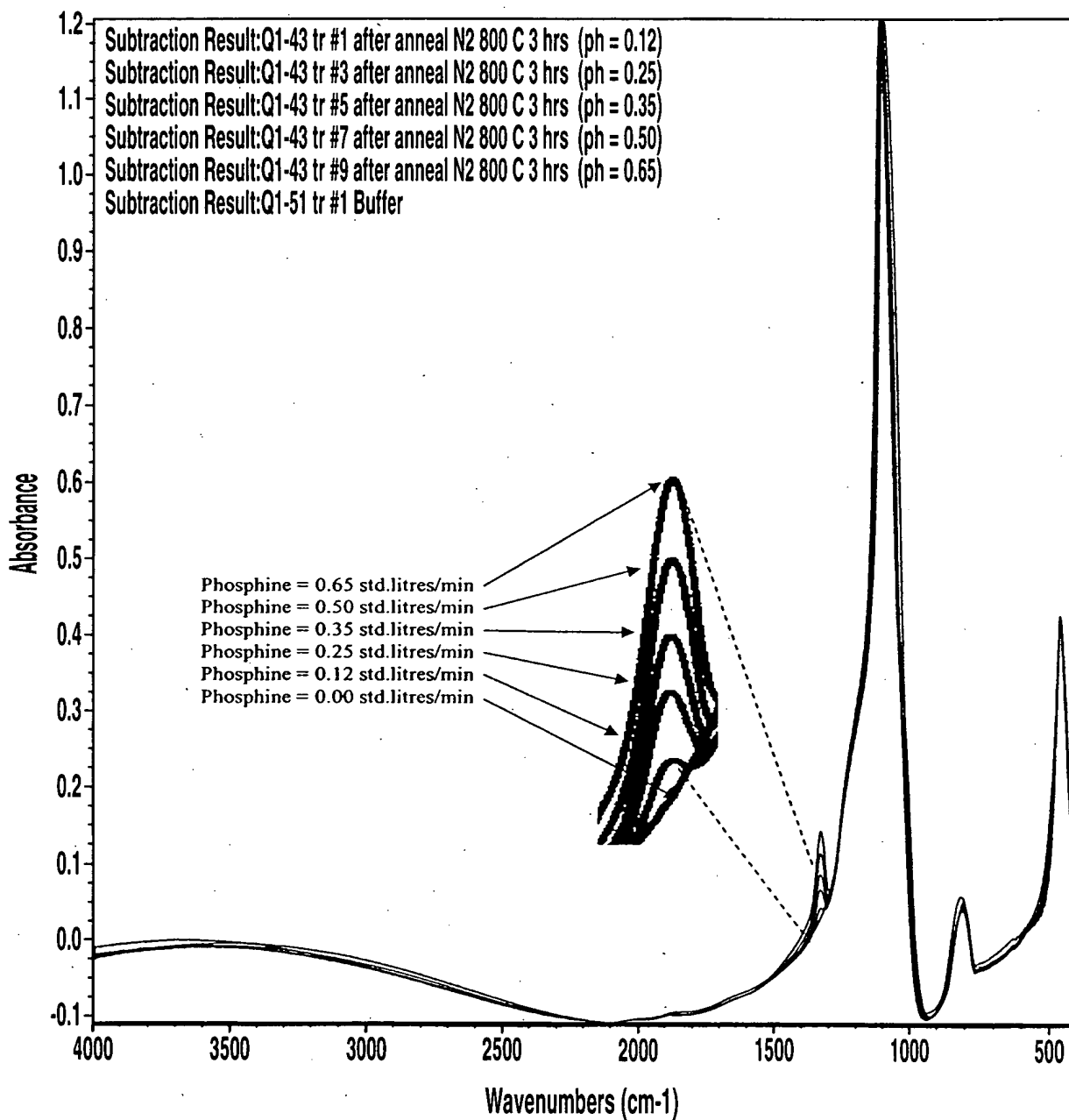


FIG. 3c



SIN 09/956,916
A14 1762

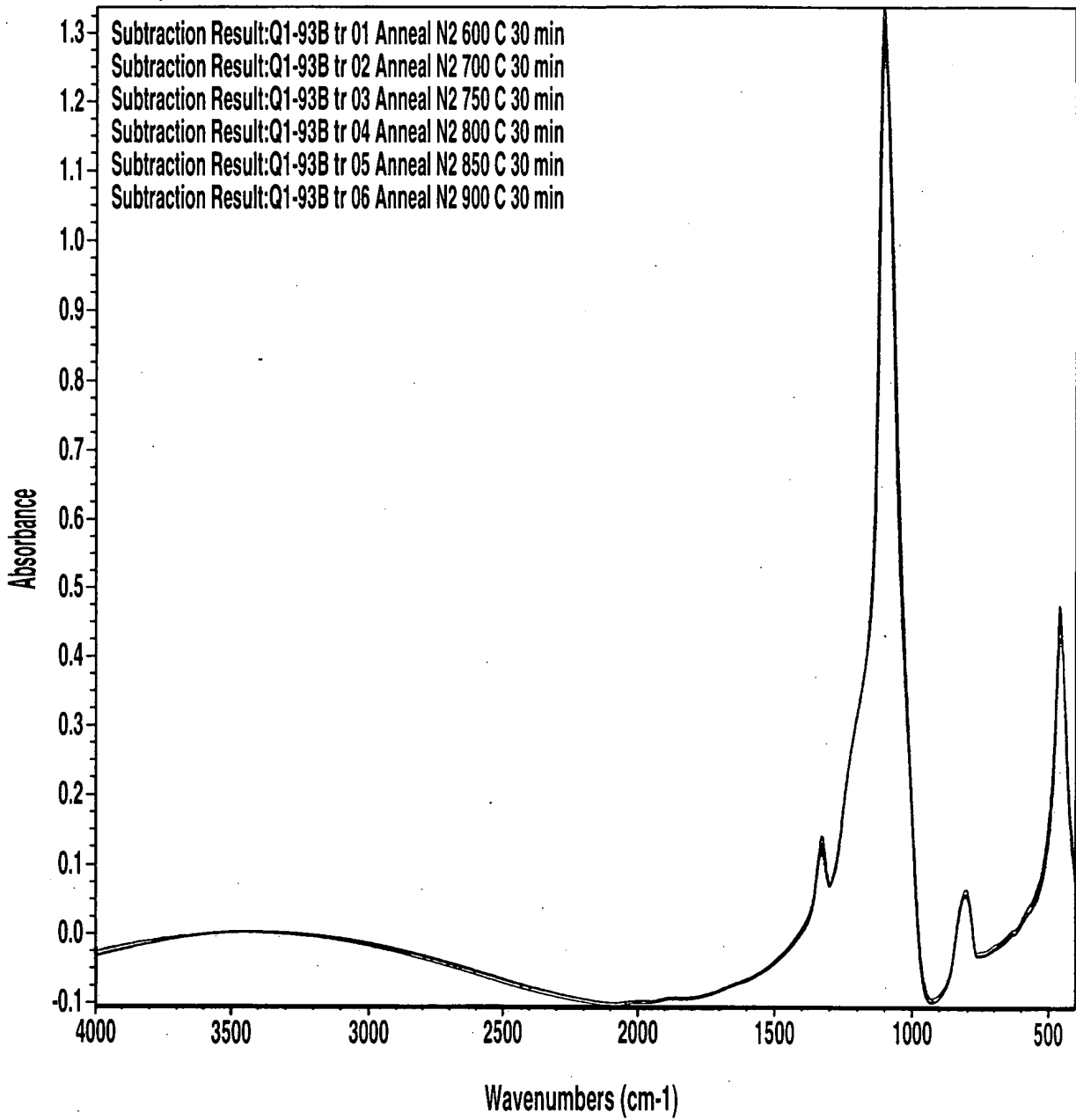


FIG. 3d



S/N 09/956,916
A14 1762

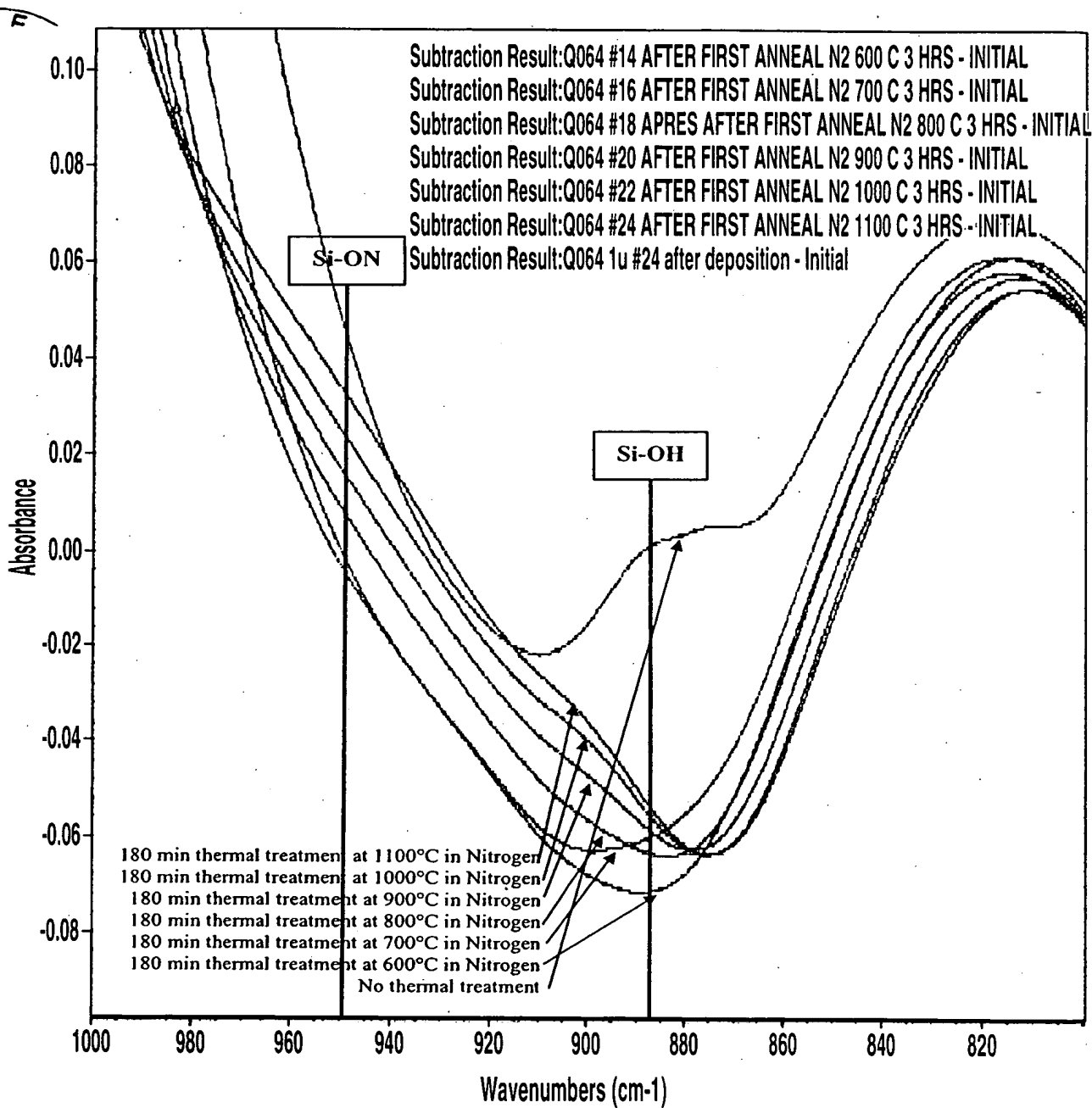
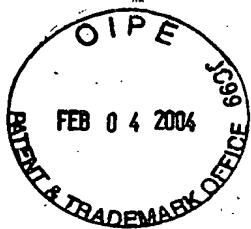


FIG. 4a



SIN 09/956,916
A1U 1762

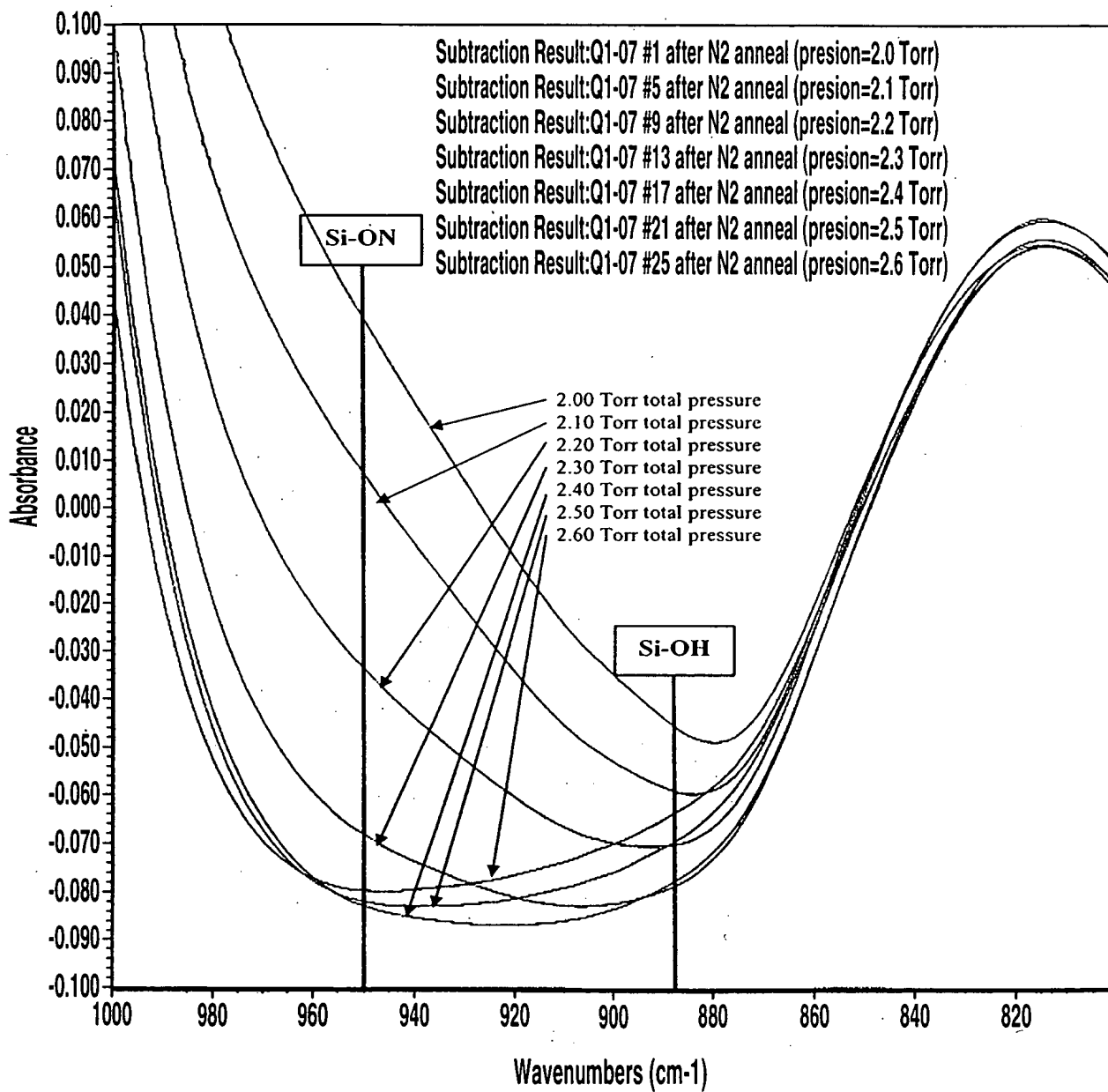


FIG. 4b



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Att 1762

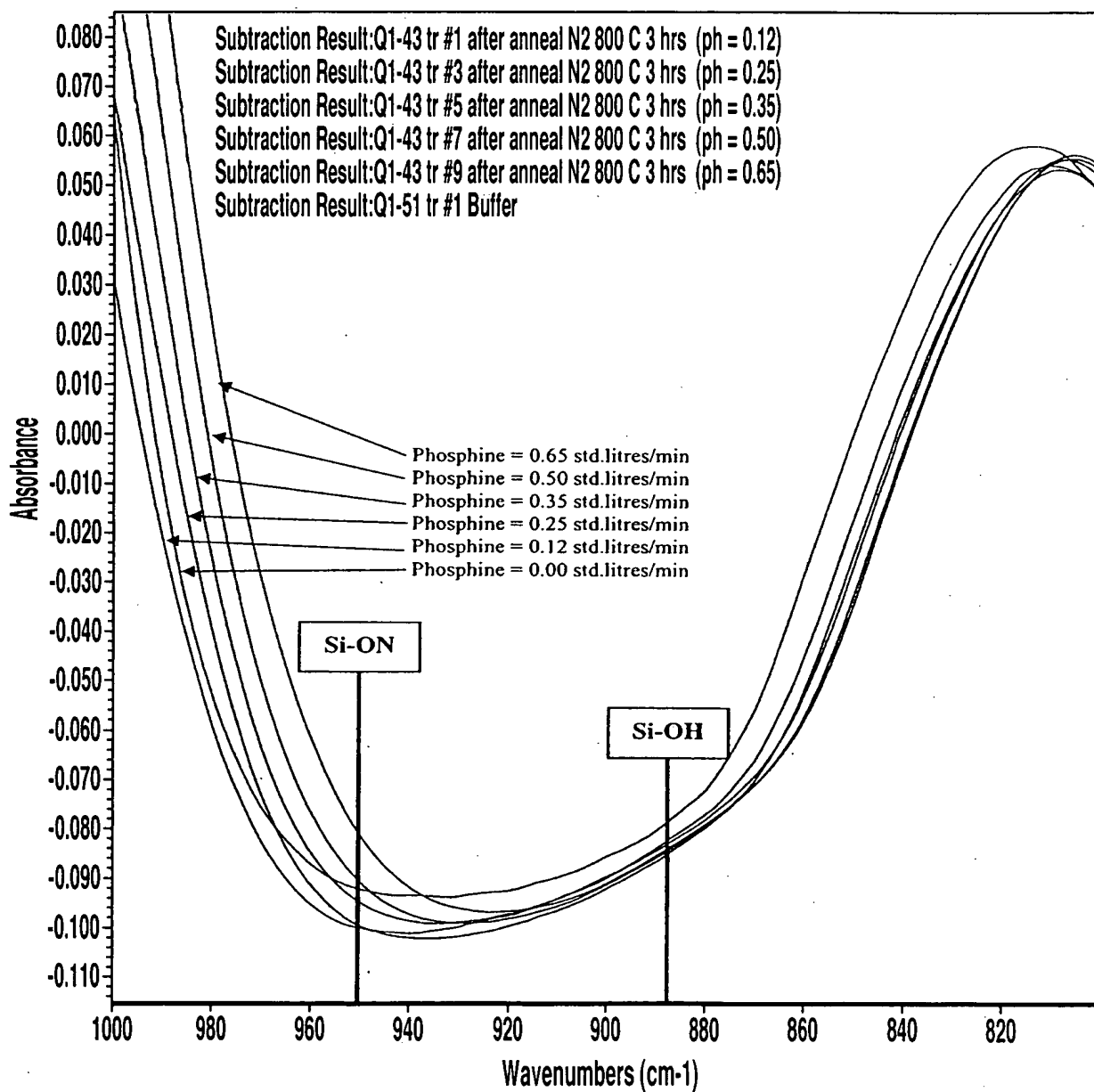


FIG. 4c



SIN 09/956,916
A/U 1762

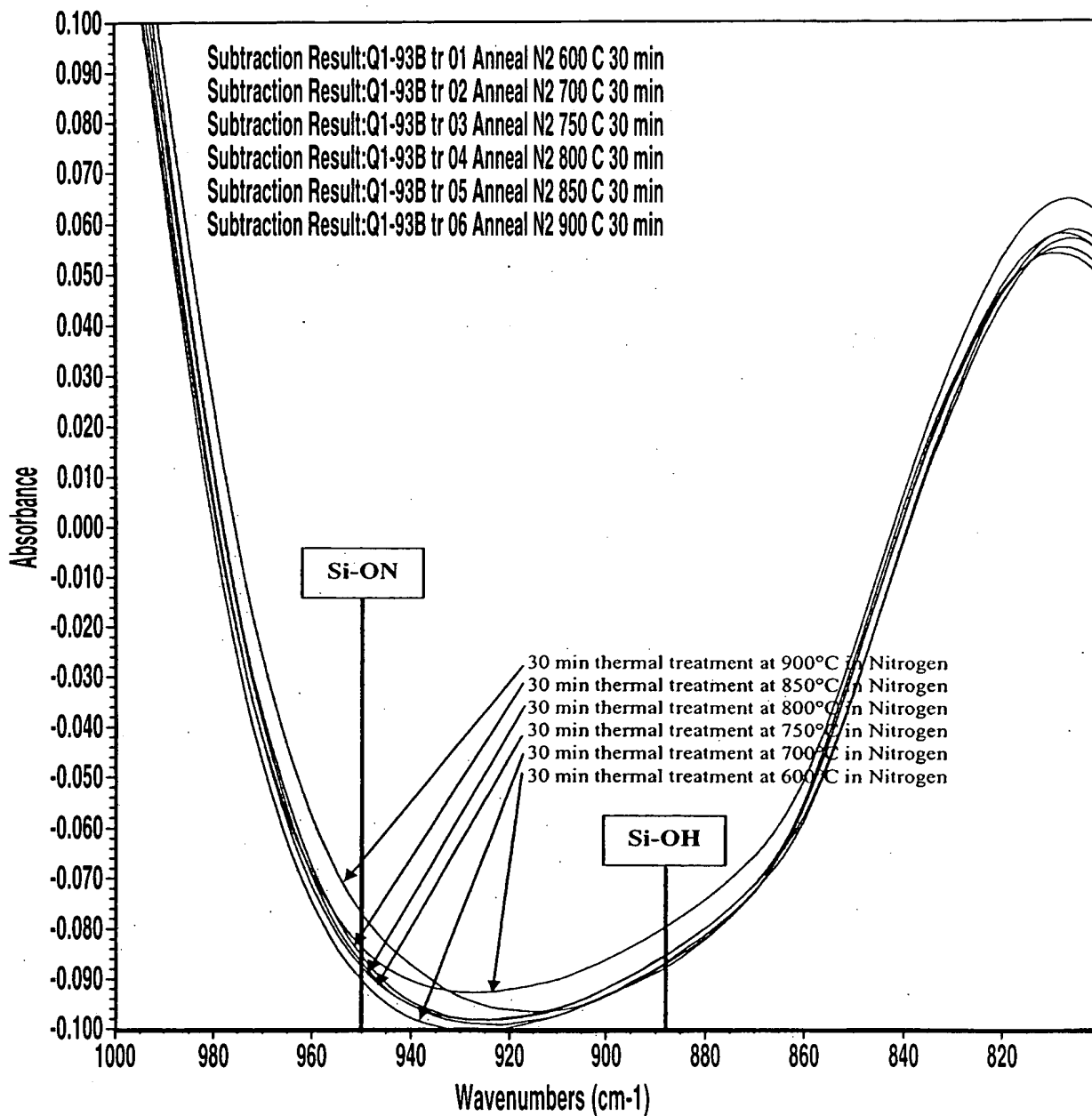


FIG. 4d



SIN 09/956,916
A1U 1762

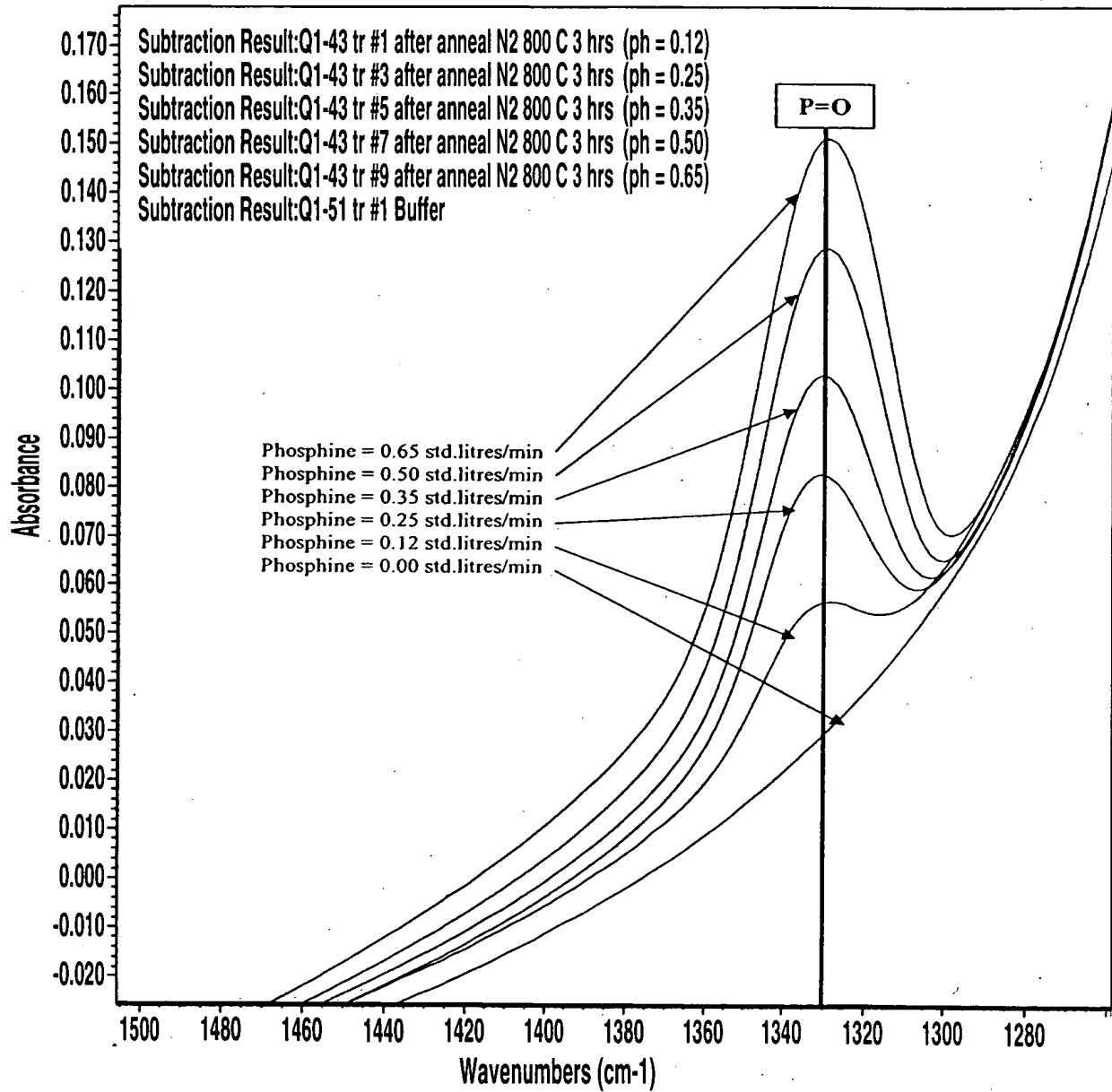


FIG. 5c



SIN 09/956,916
A1U 1762

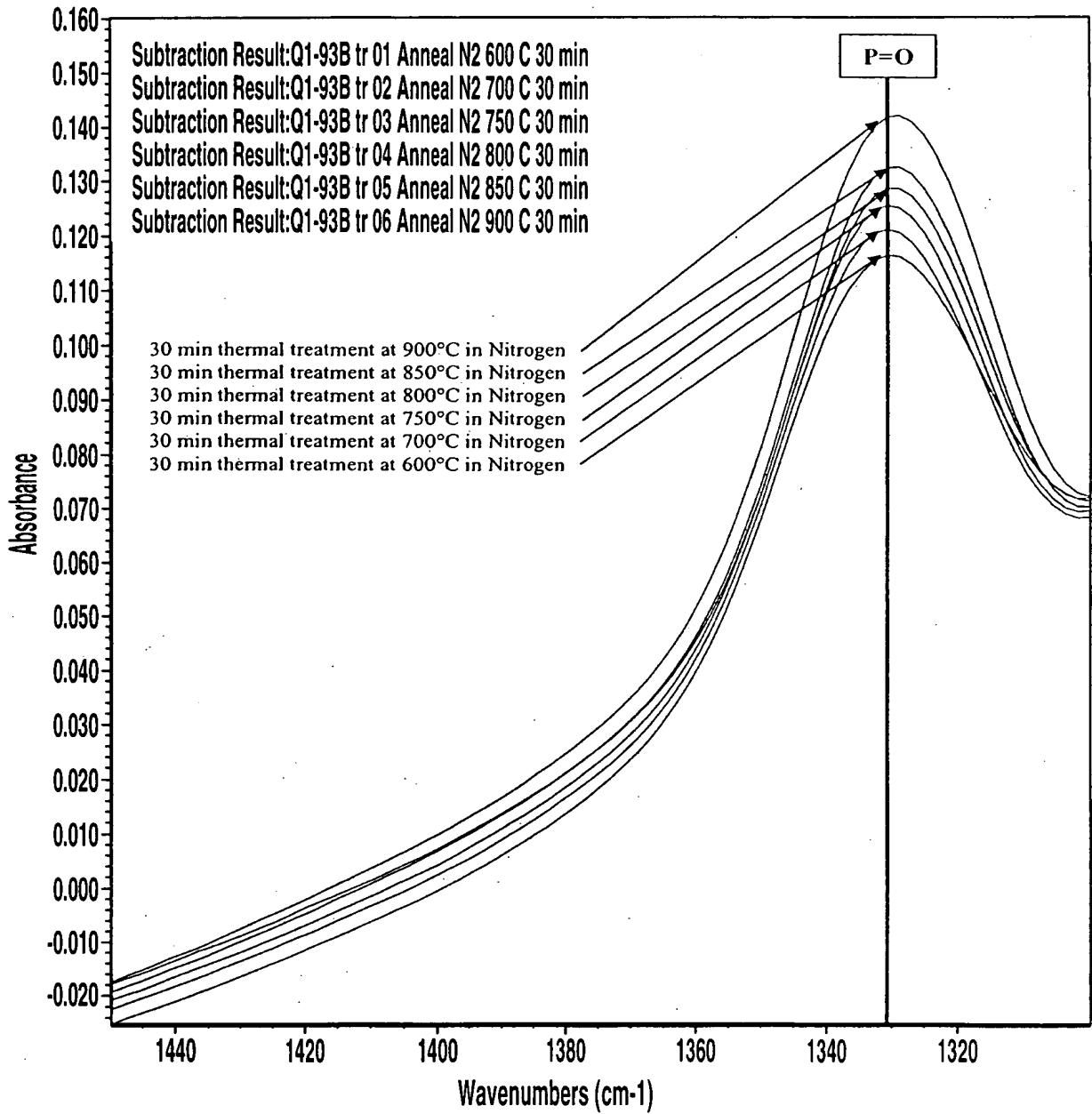


FIG. 5d



S/N 09/956,916
A/U 1762

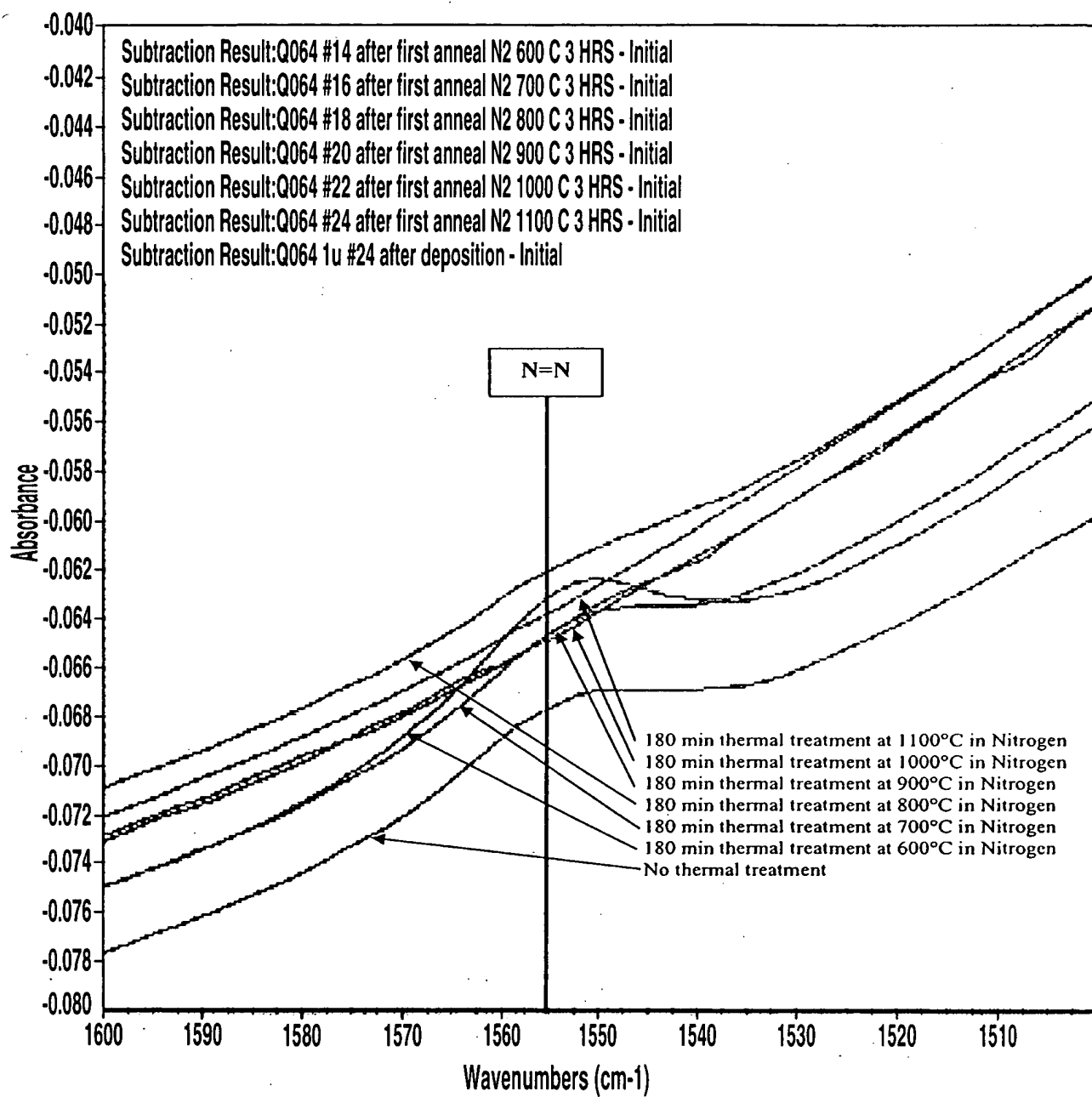


FIG. 6a



S/N 09/956,916
A14 1762

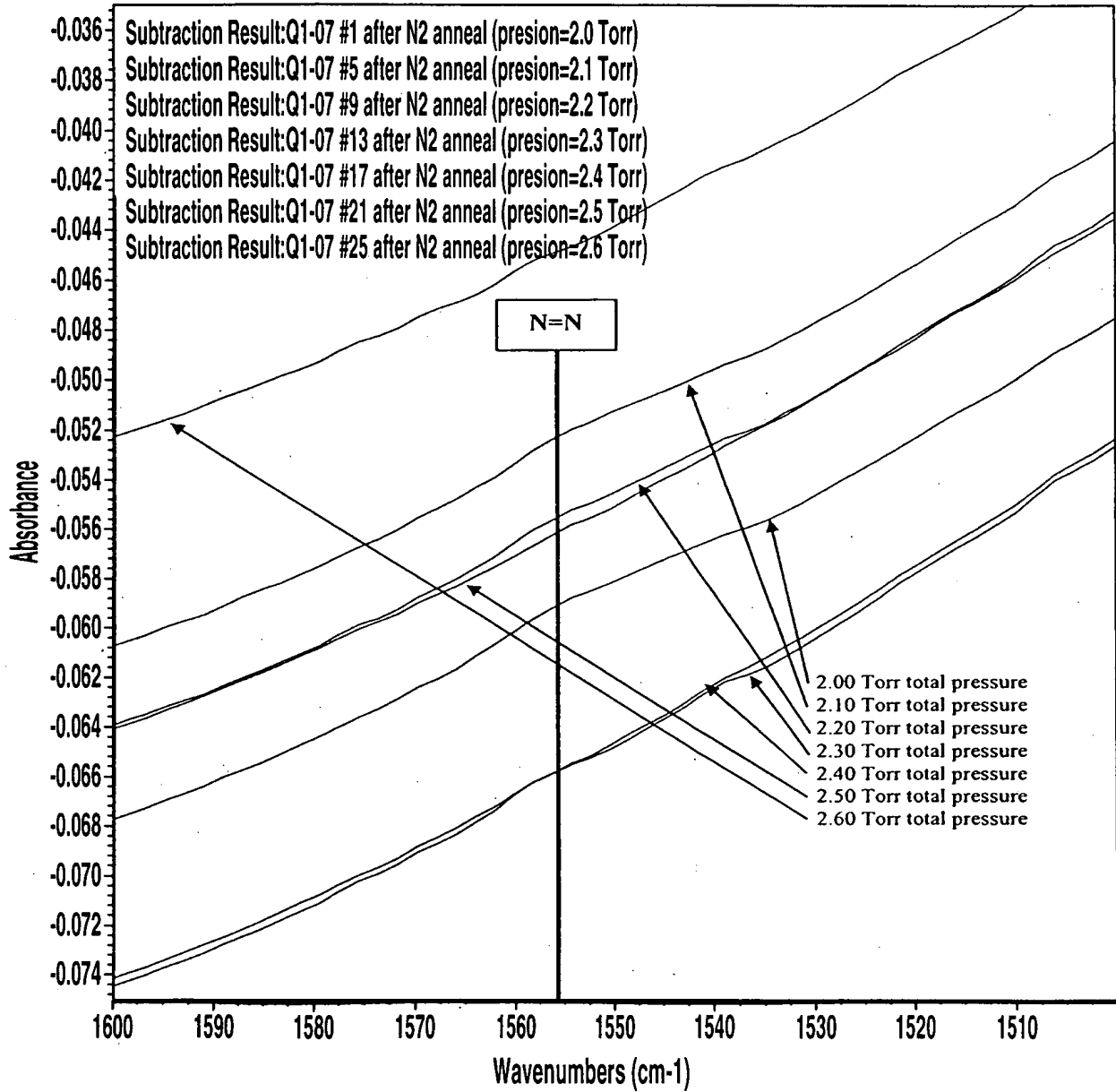


FIG. 6b



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A/U 1762

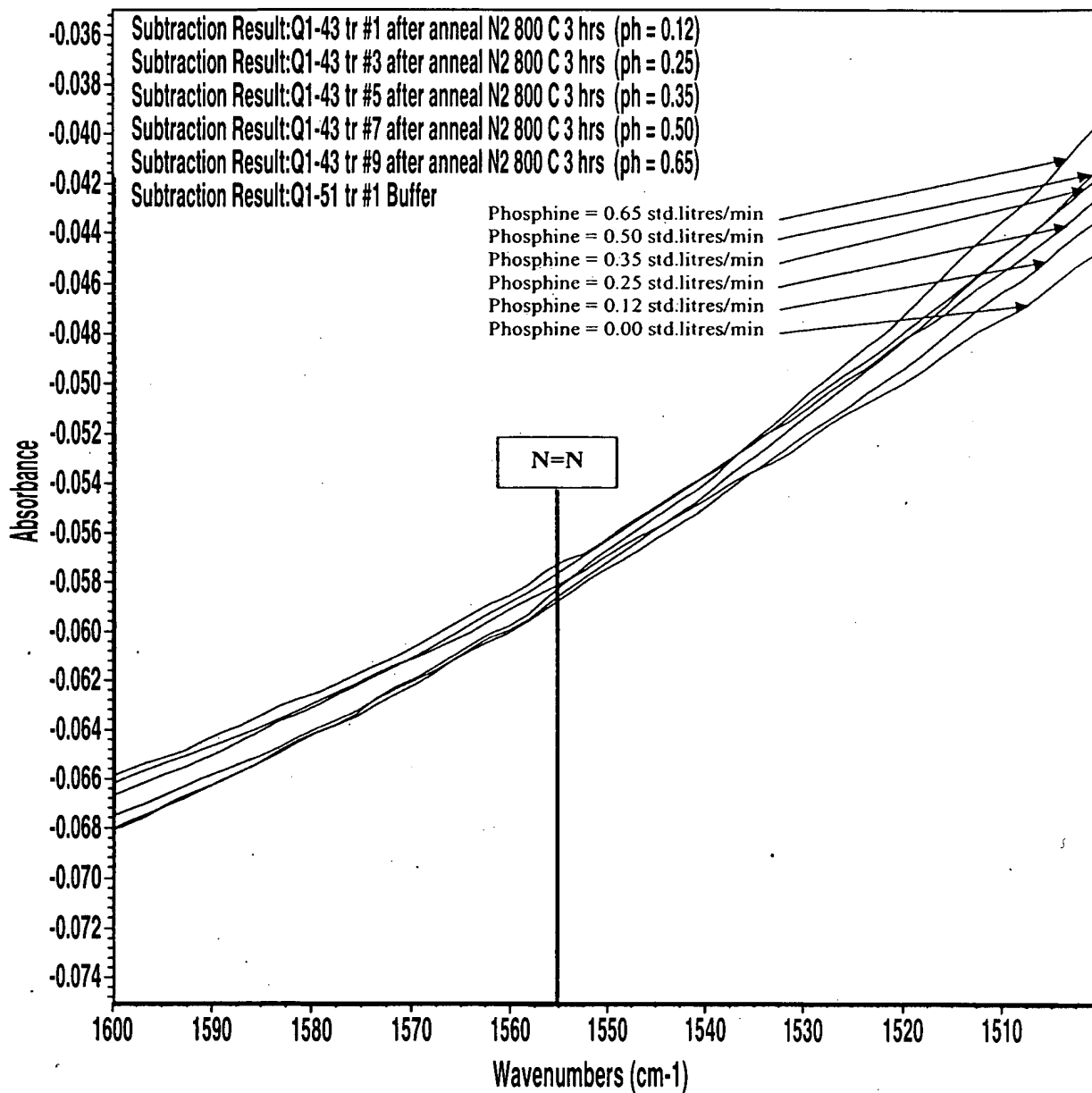
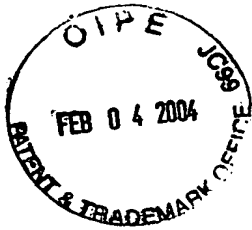


FIG. 6c



S/N 09/956,916
A14 1762

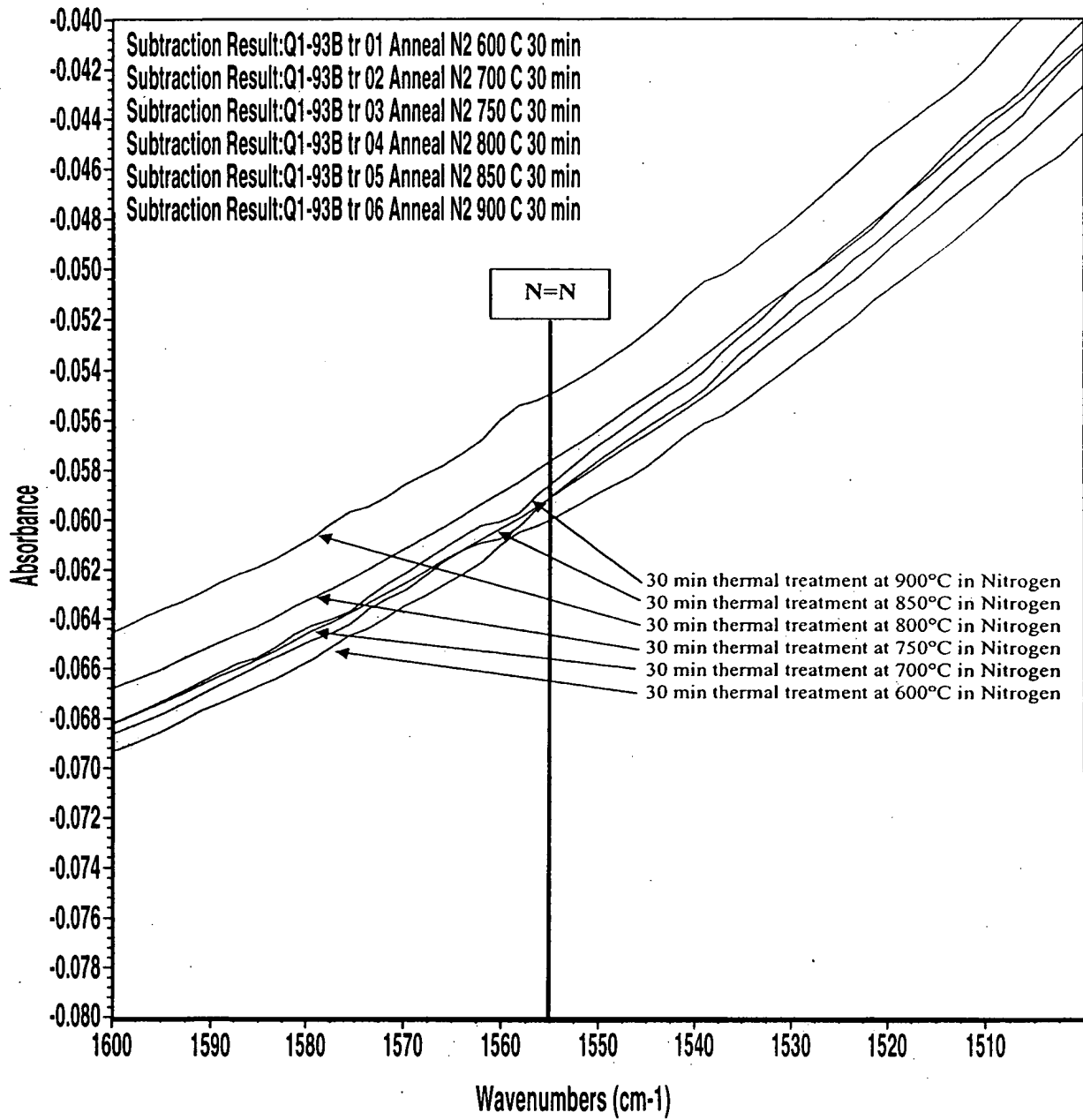


FIG. 6d



SIN 09/956,916
A1U 1762

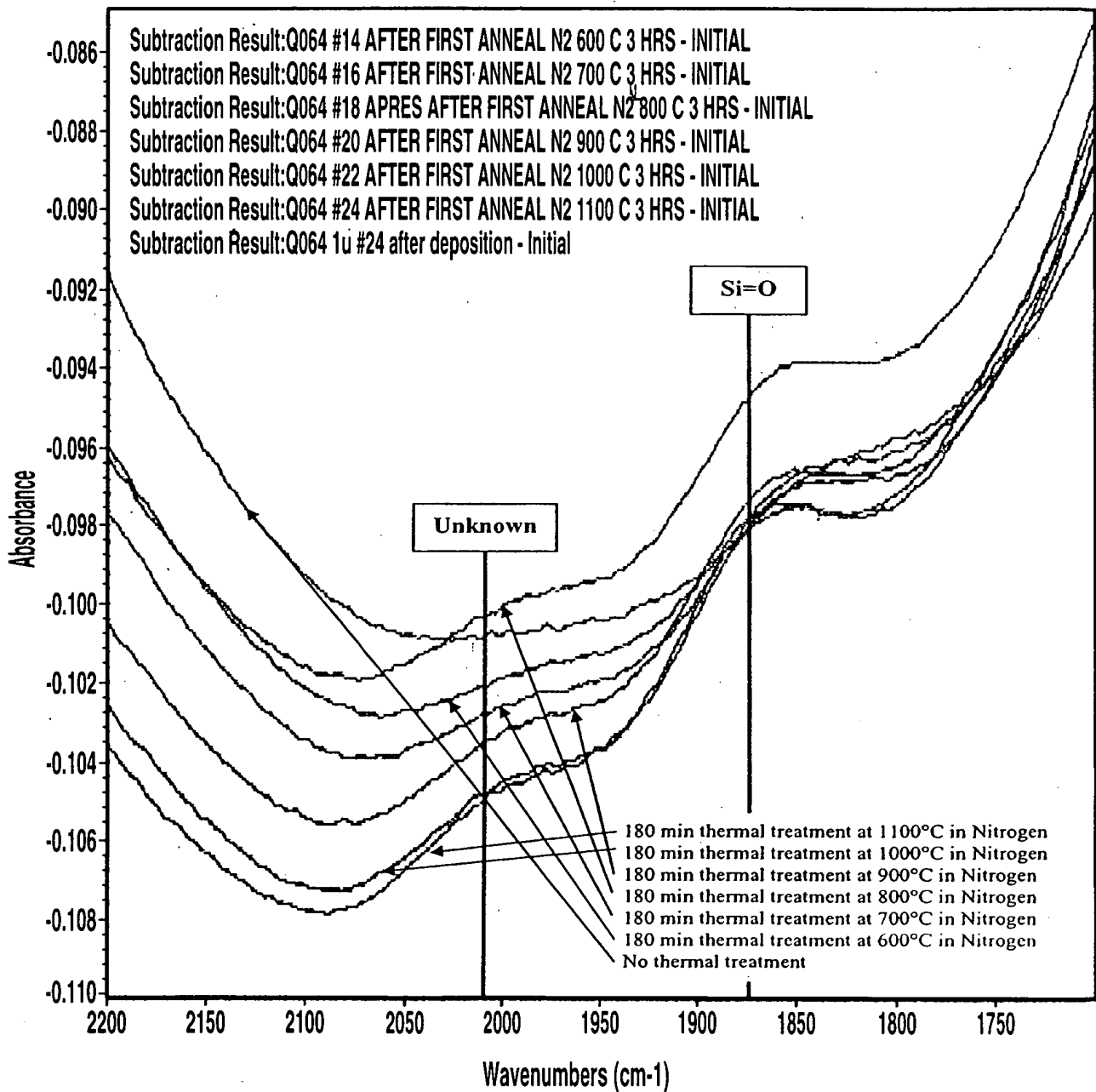


FIG. 7a



SIN 09/956,916
A1U 1762

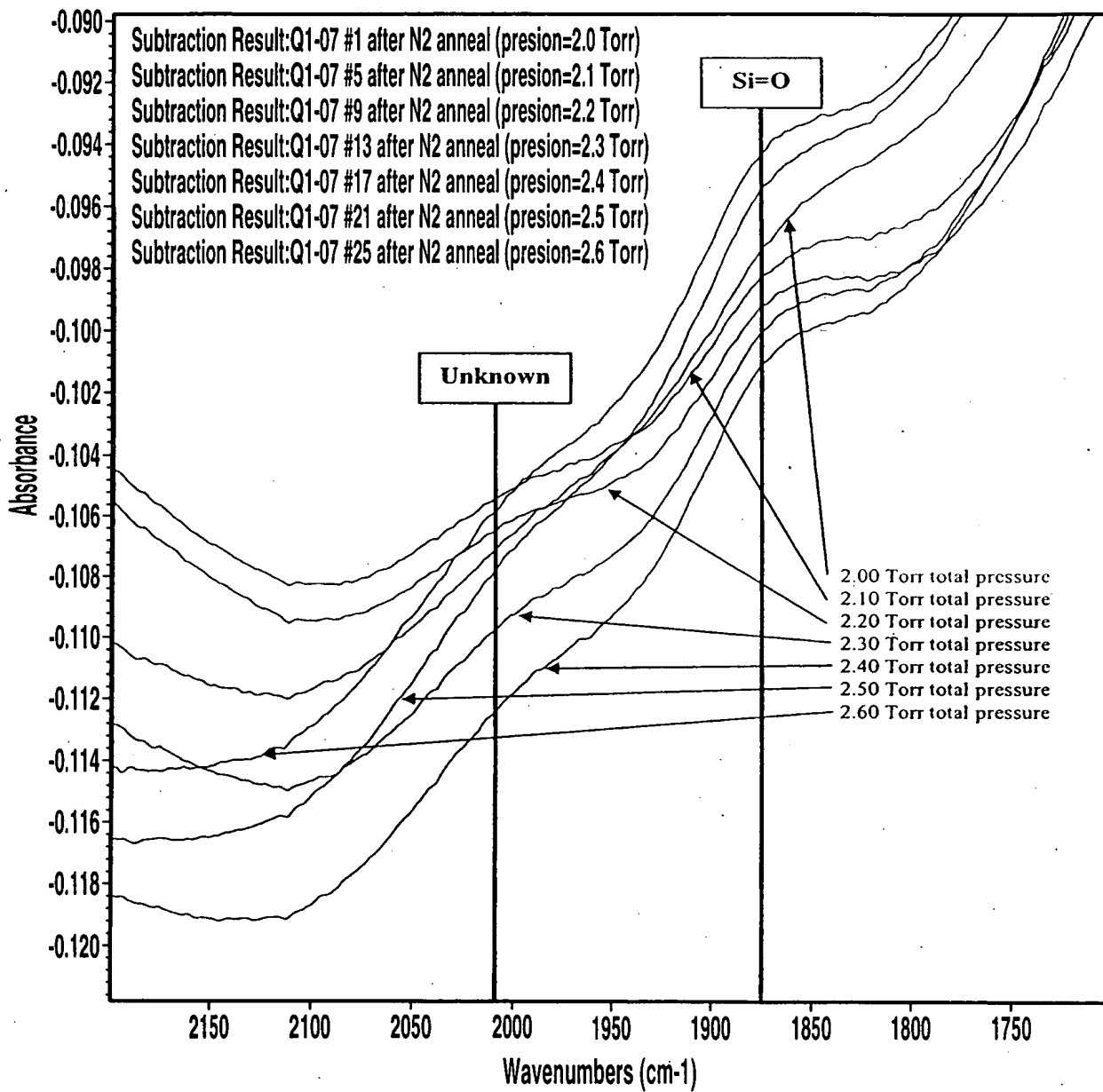


FIG. 7b



SIN 09/956,916
A14 1762

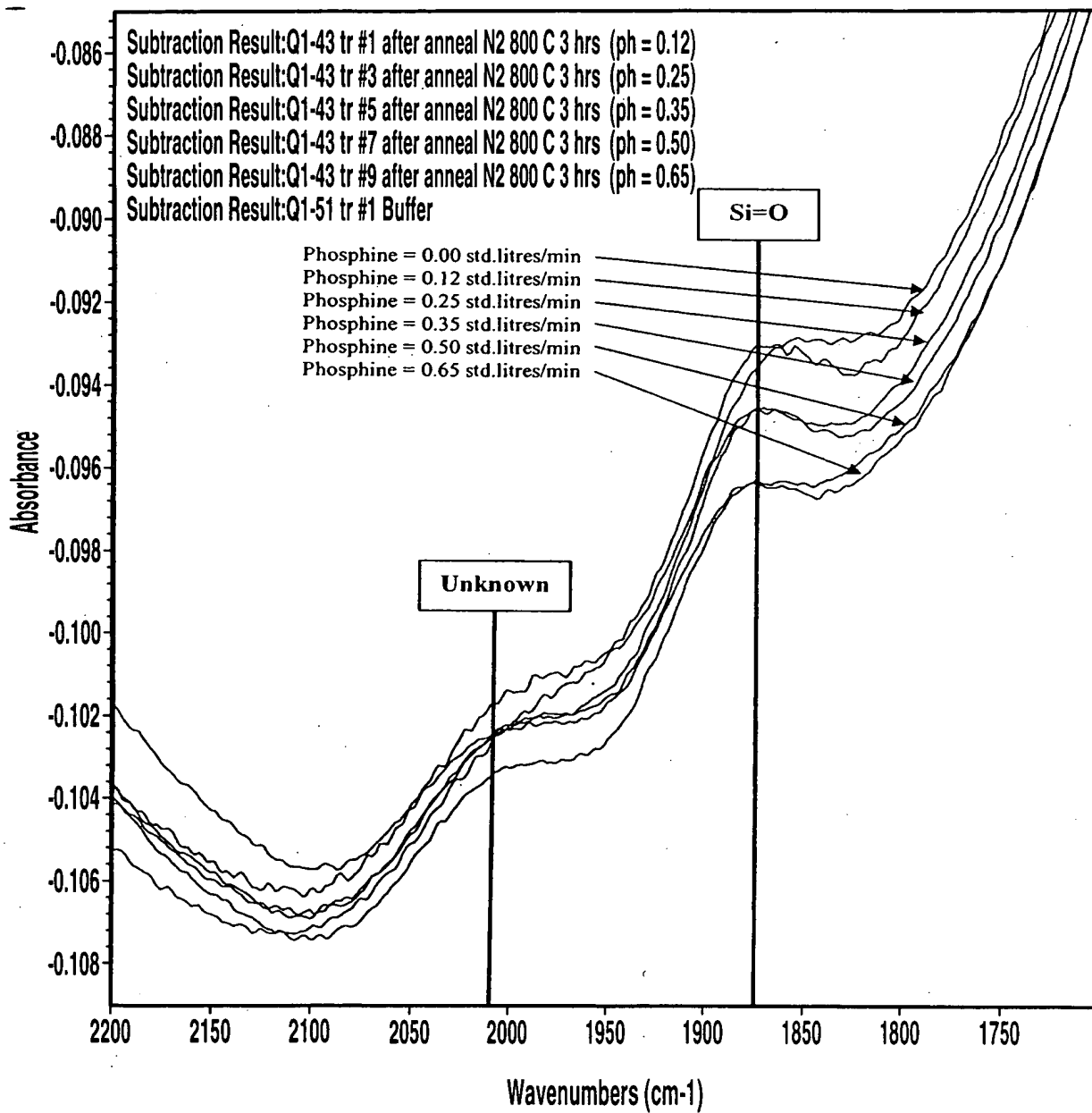


FIG. 7c



SIN 09/956,916
A1U 1762

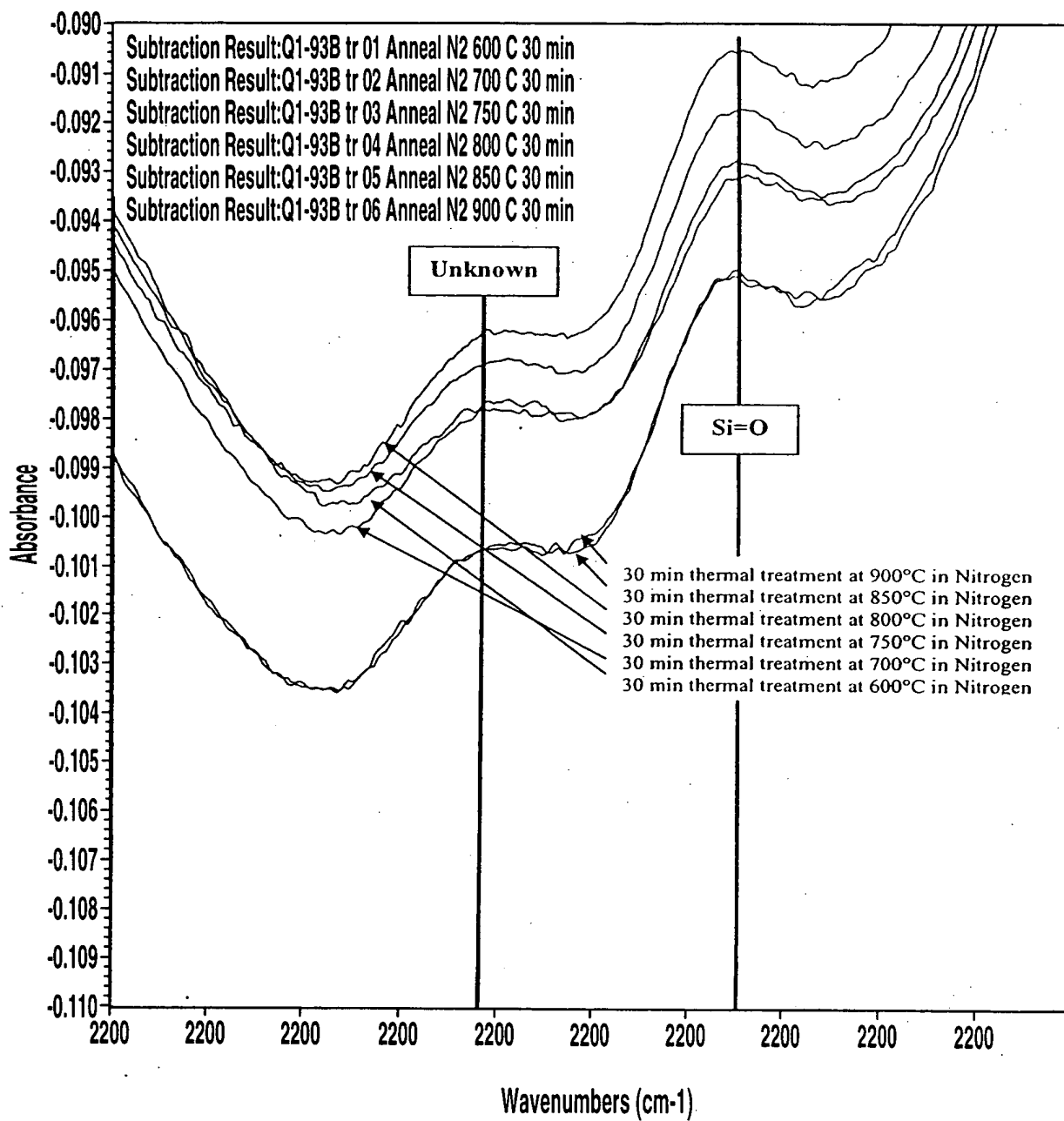
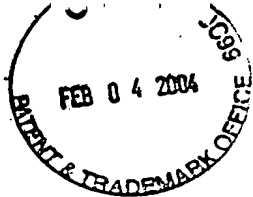


FIG. 7d



S/N 09/956,916
AIU 1762

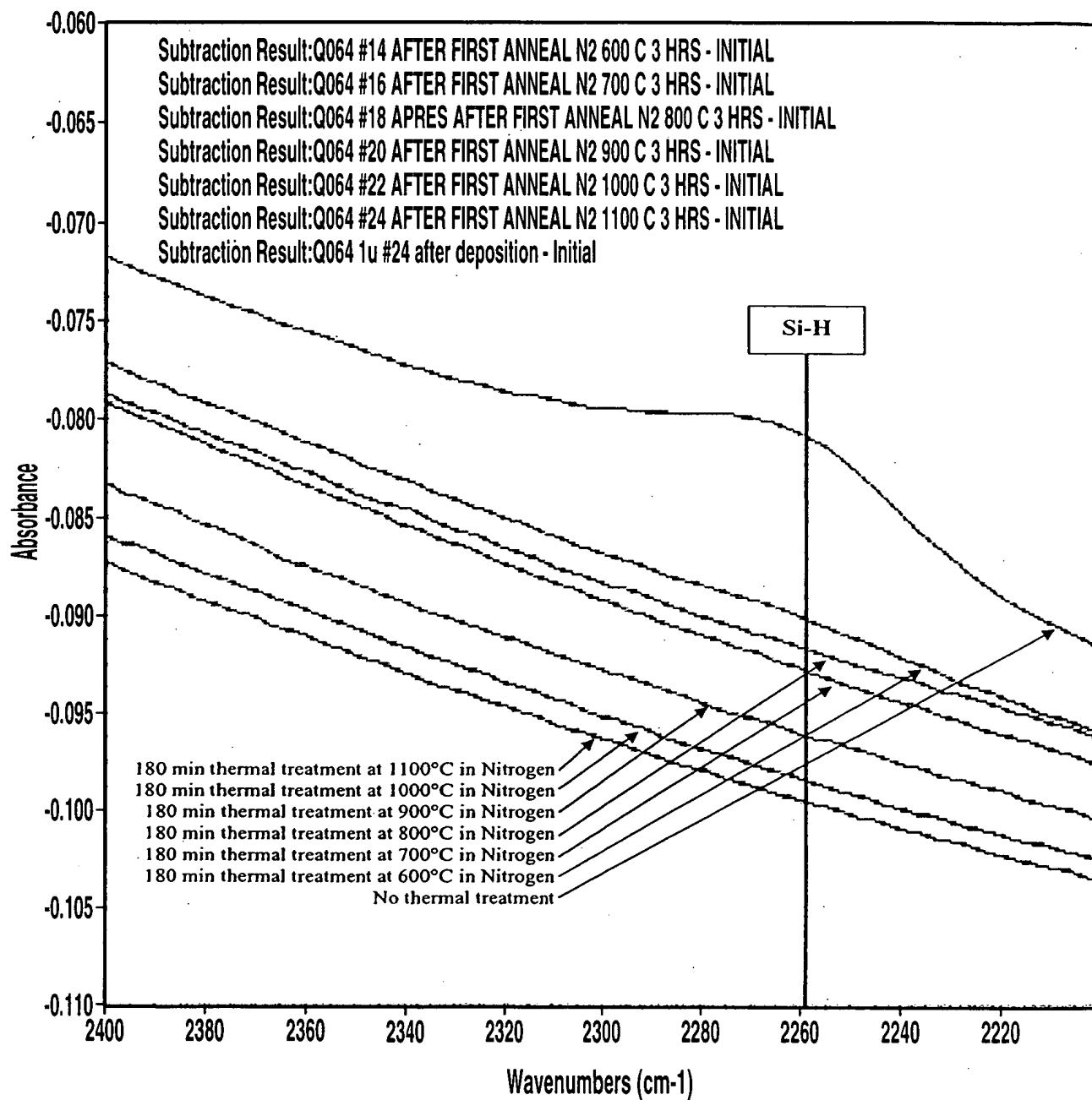
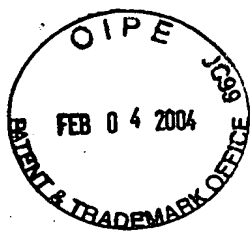


FIG. 8a



OIPE

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A1U 1762

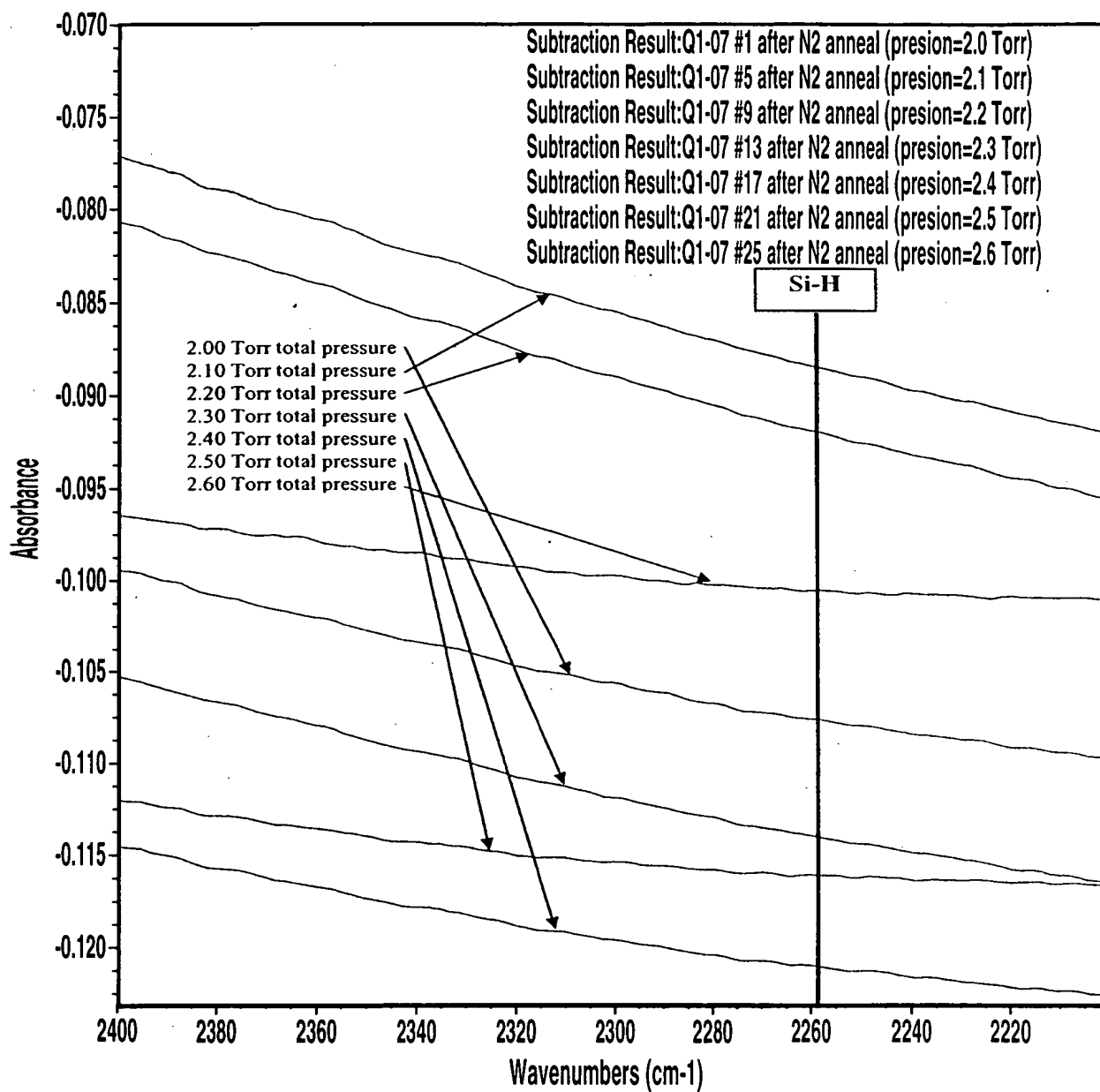


FIG. 8b



S/N 09/956,916
Att 1762

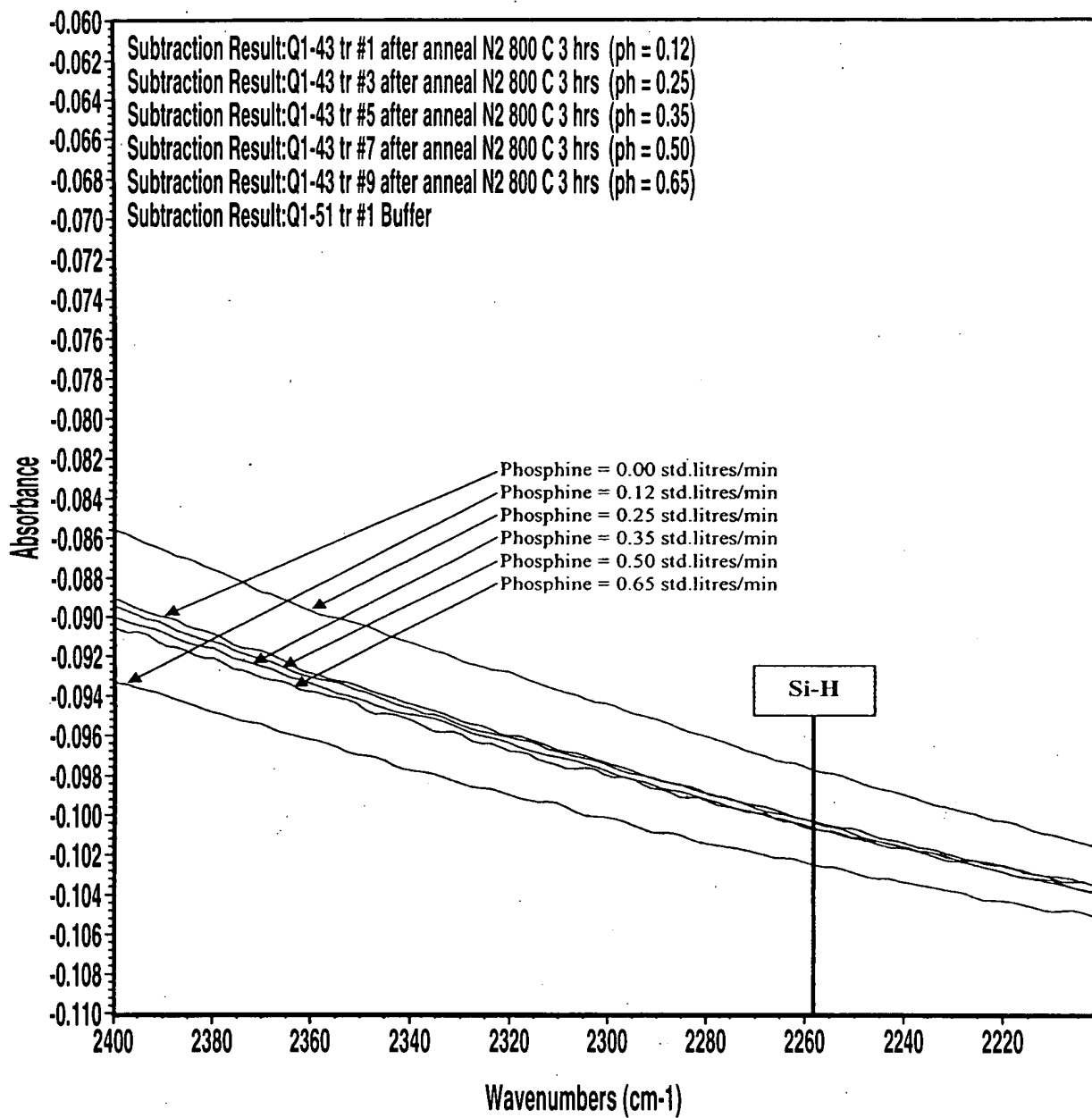


FIG. 8c



S/N 091956,916
A/u 1762

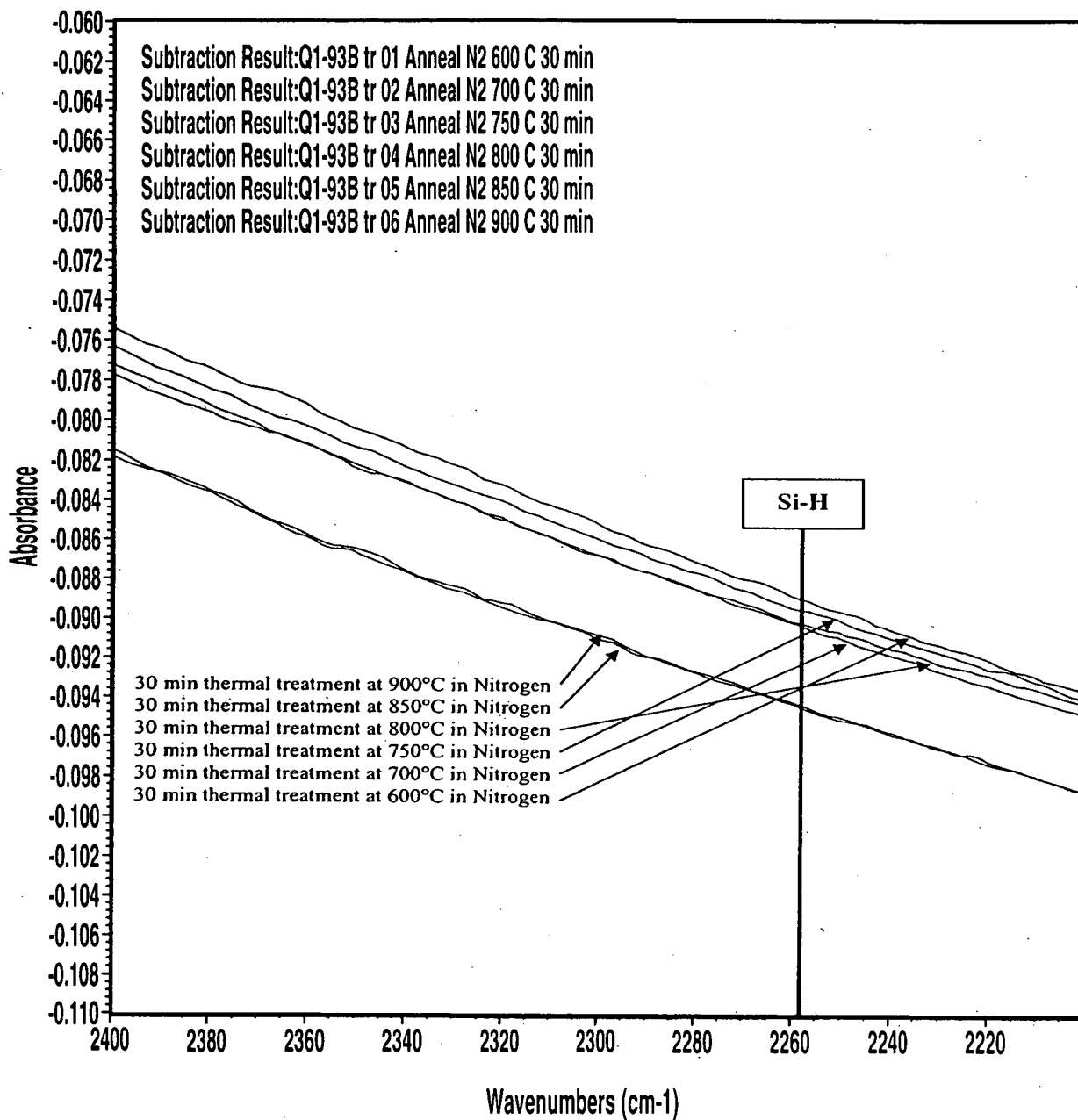
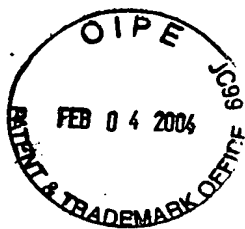


FIG. 8d



SIN 09/956,916
A1U 1762

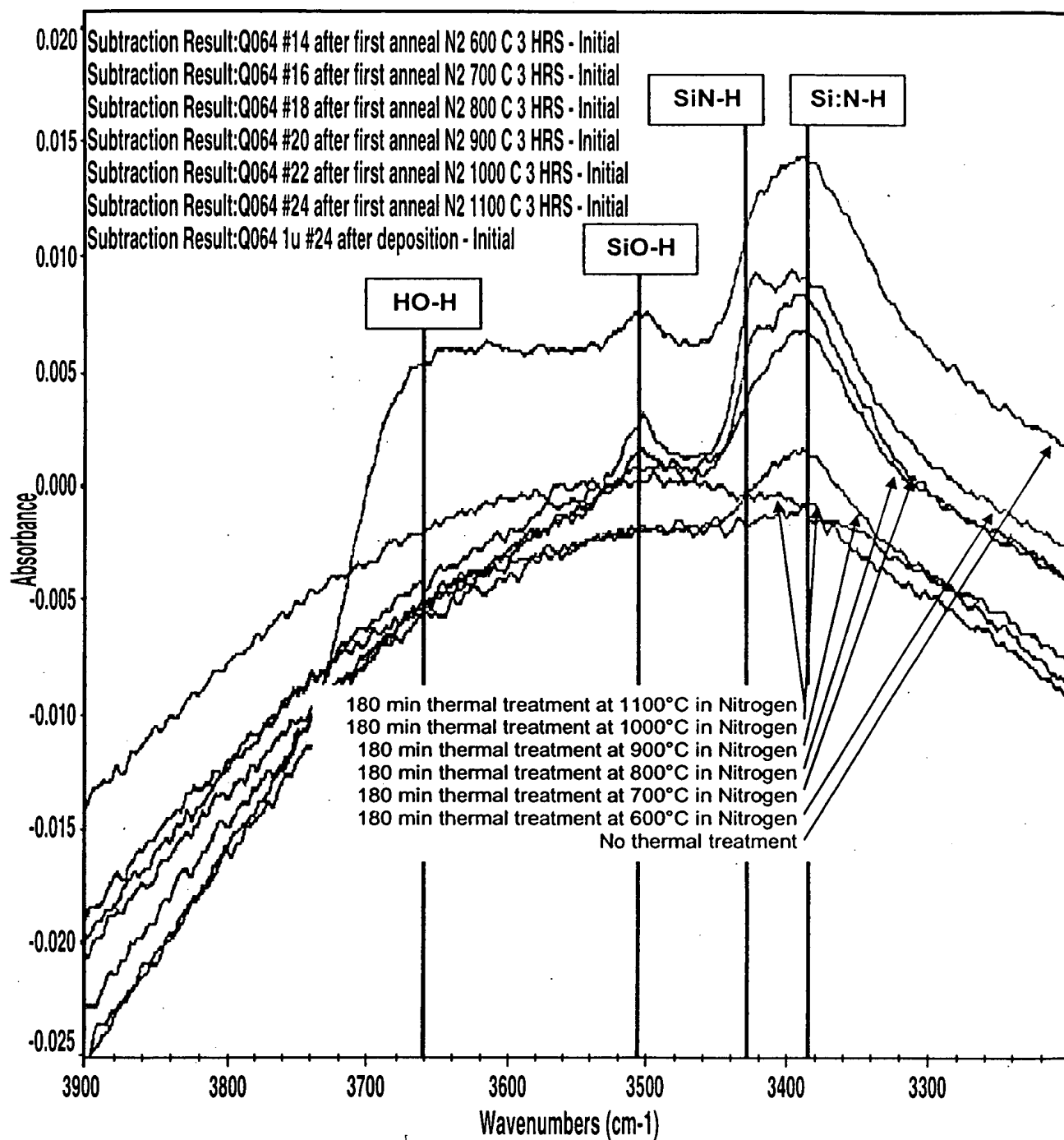


FIG. 9a



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A/U 1762

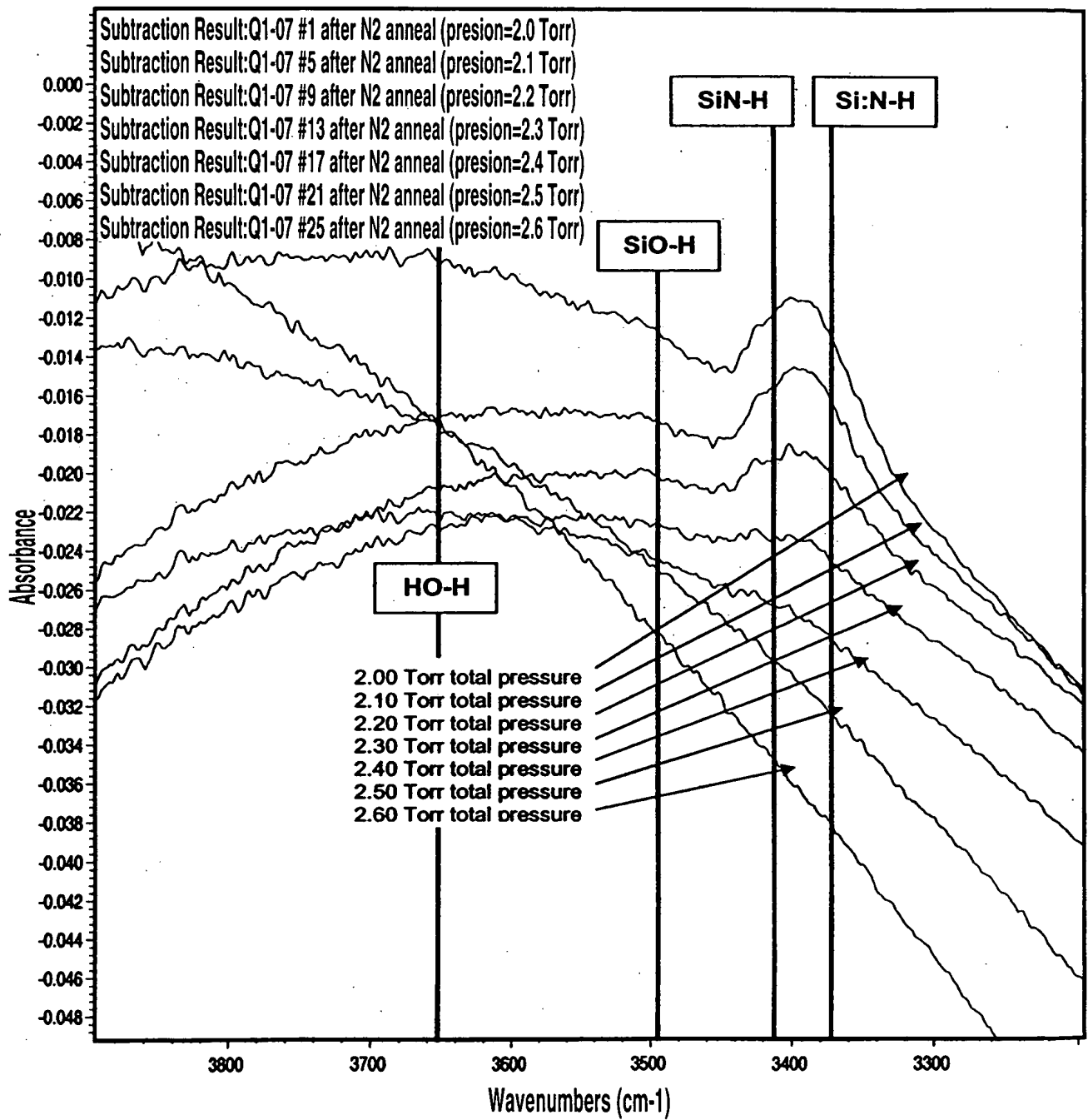


FIG. 9b



S/N 09/956,916
A/u 1762

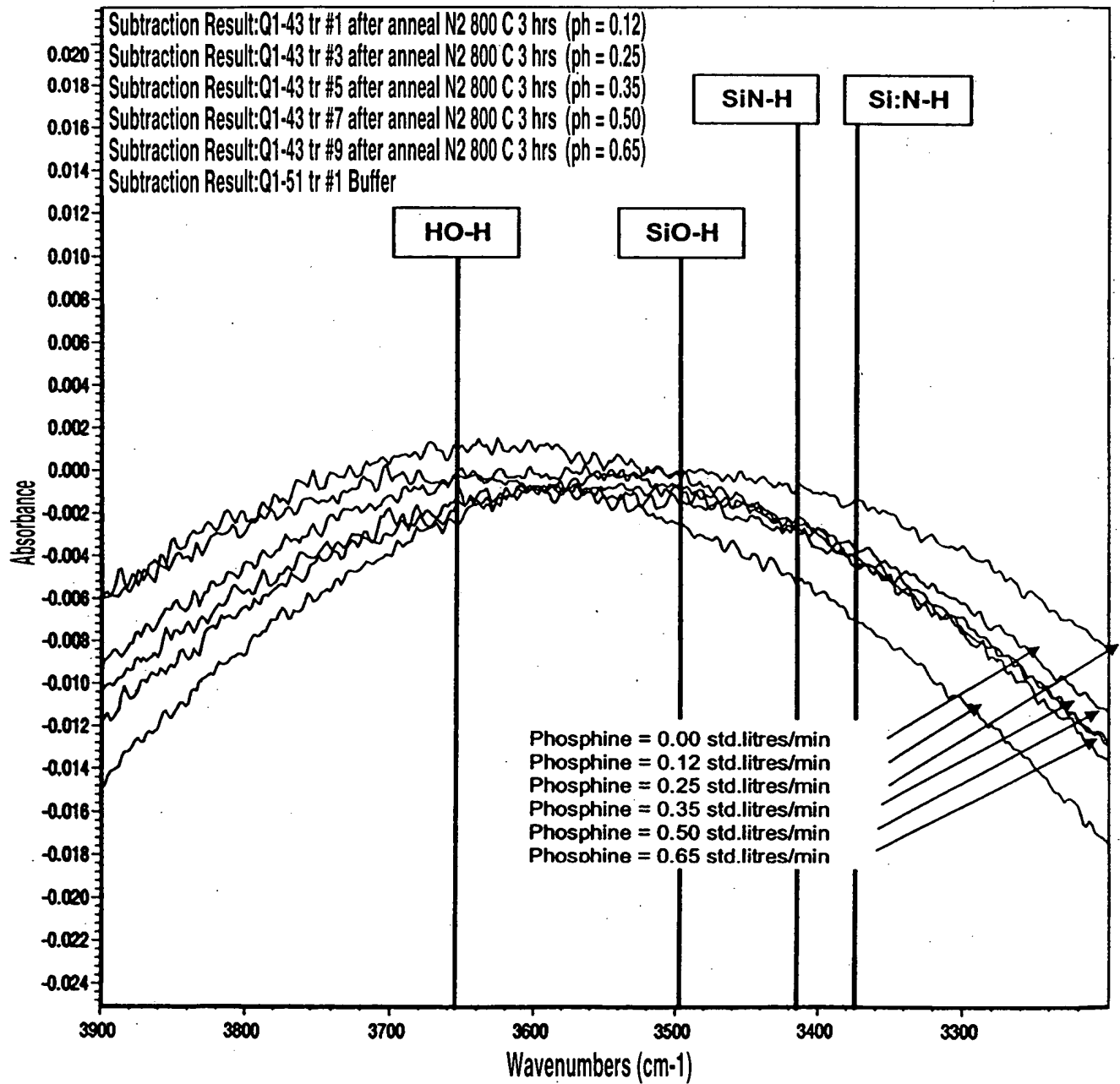


FIG. 9c



S/N 09/956,916
A/U 1762

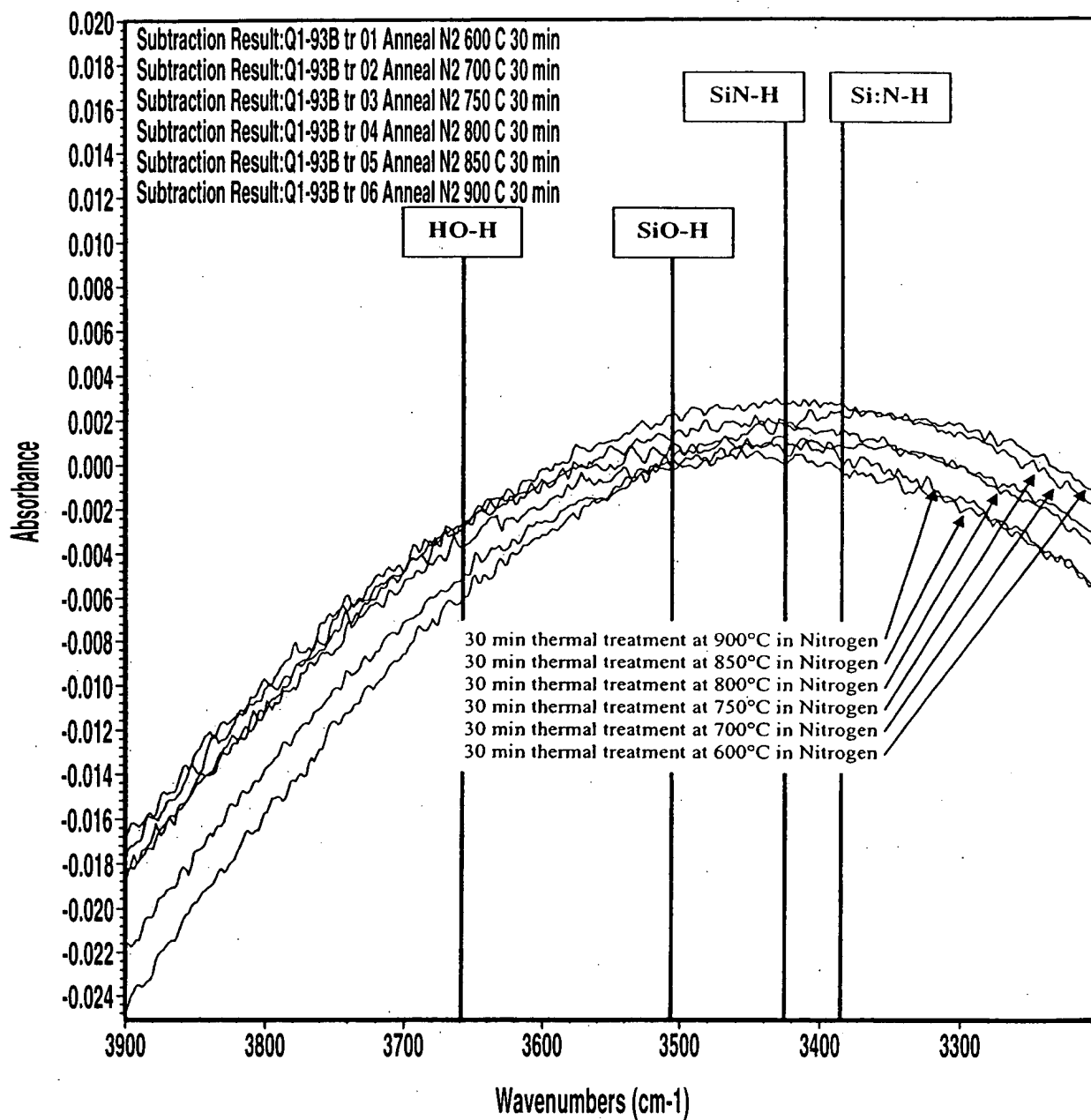


FIG. 9d



S/N 09/956,916
A1u 1762

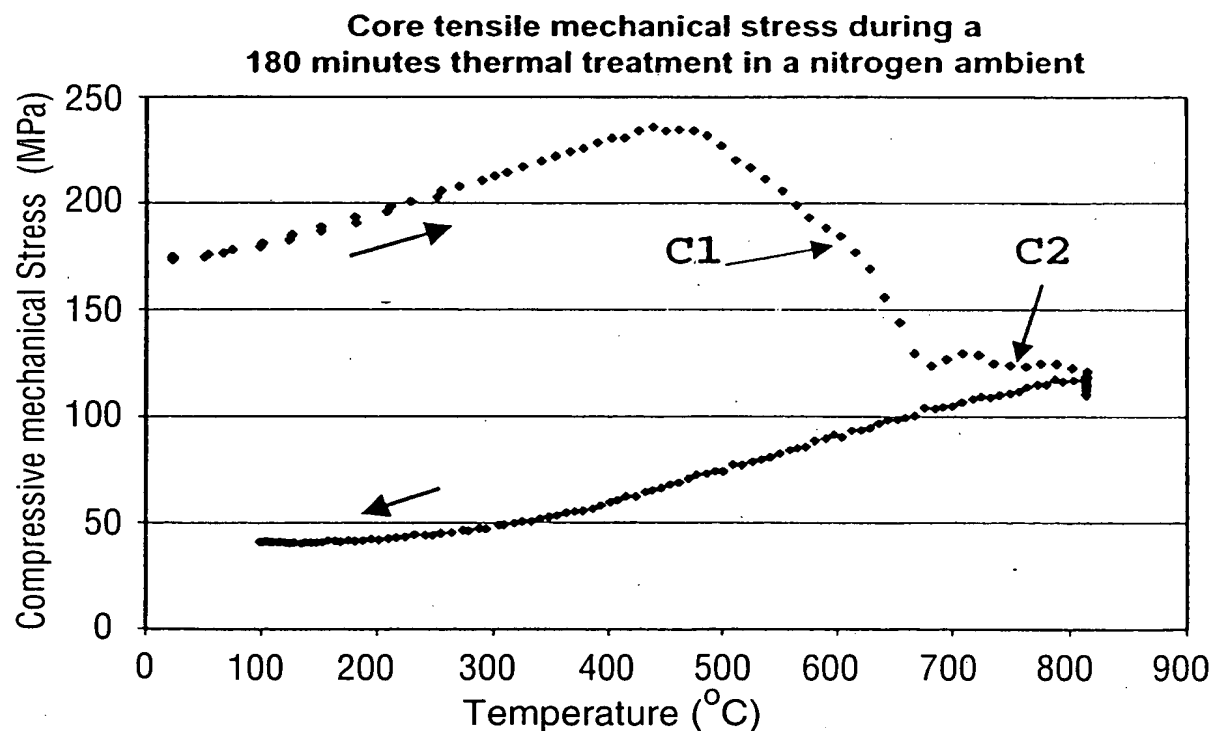
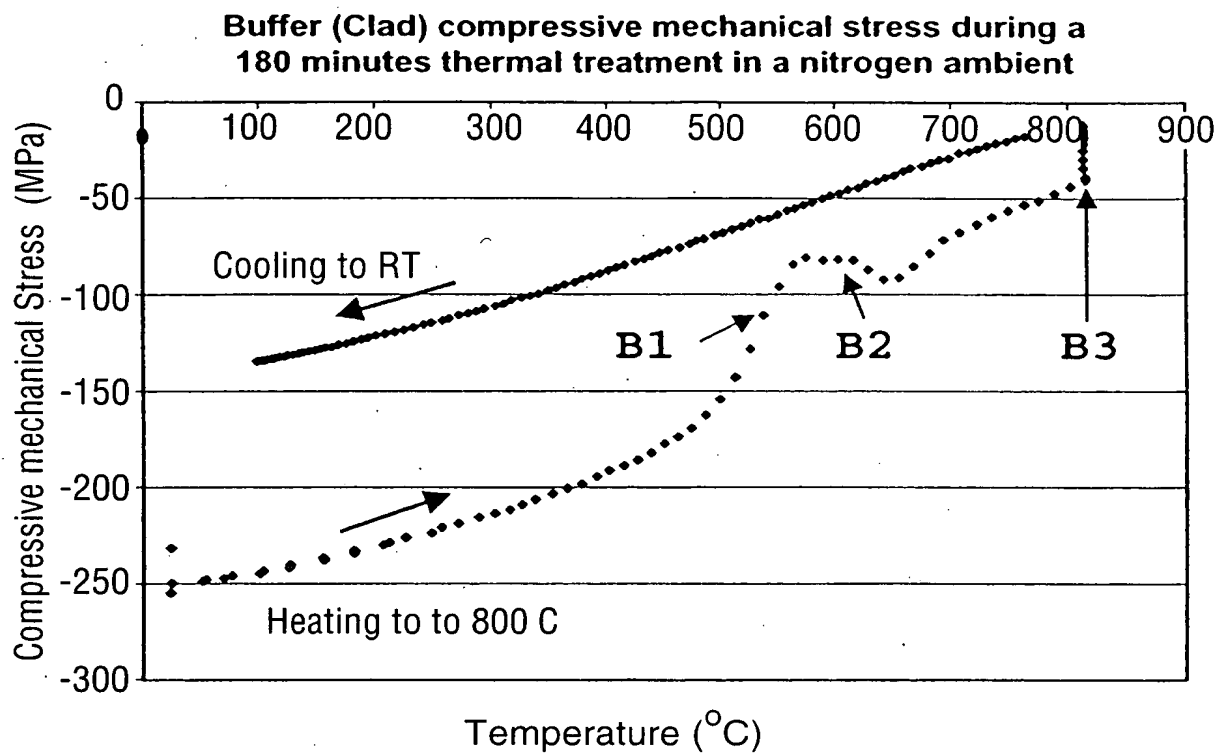


FIG. 10



S/N 09/956,916
A/U 1762

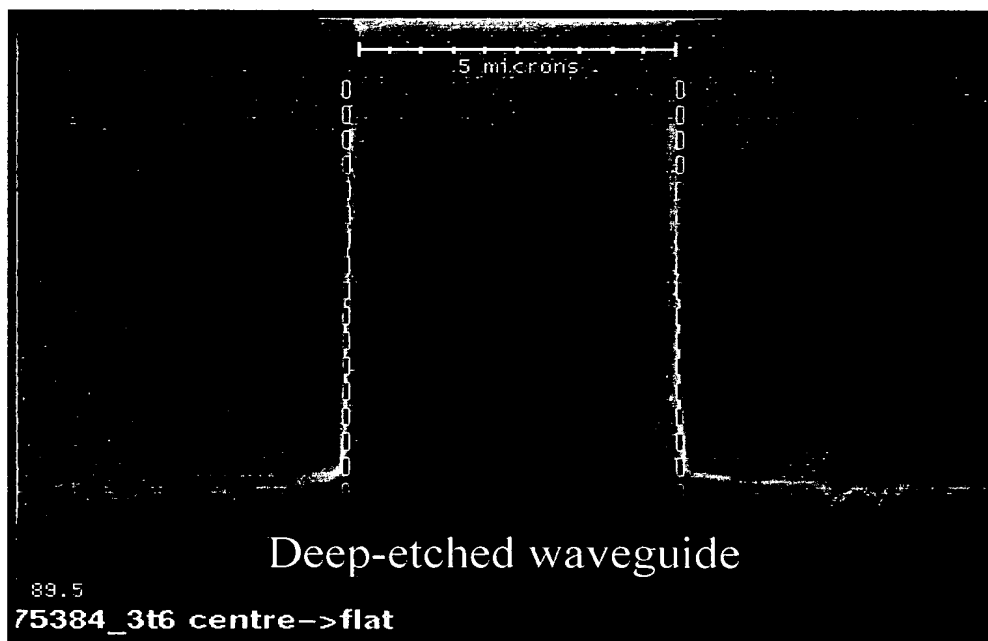
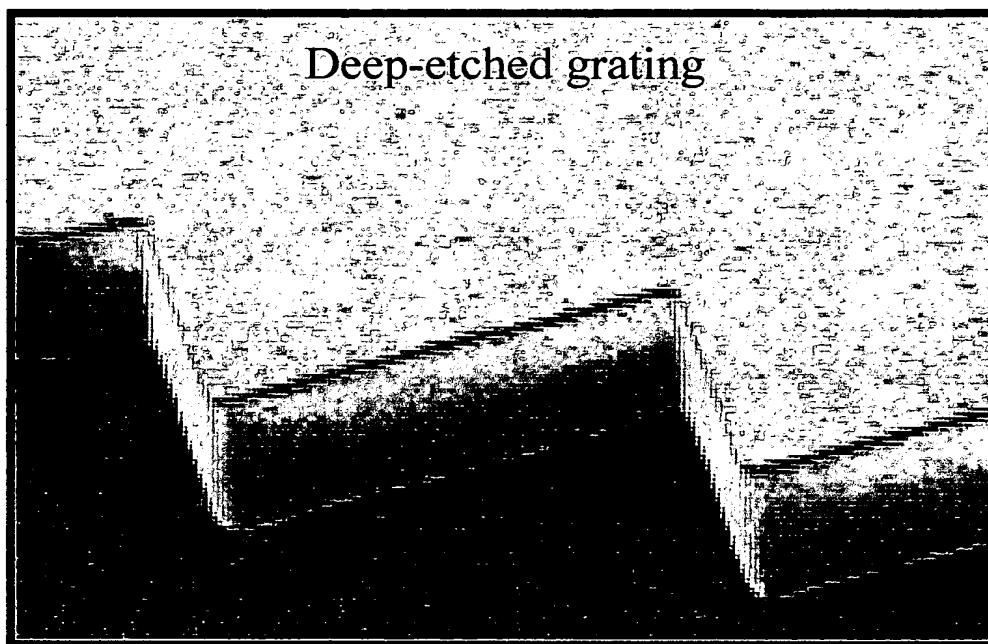


FIG. 11



S/N 09/956,916
A/u 1762

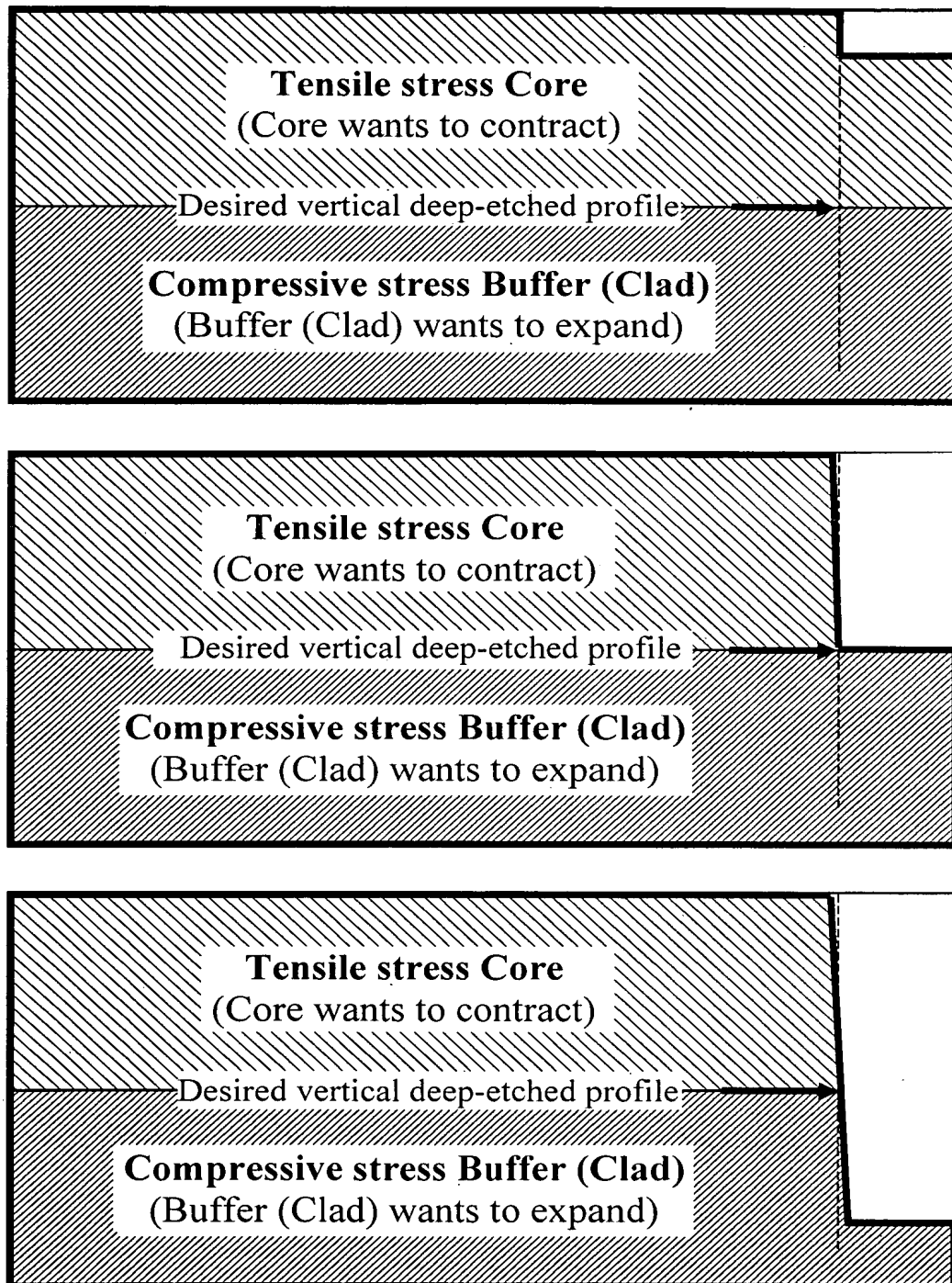
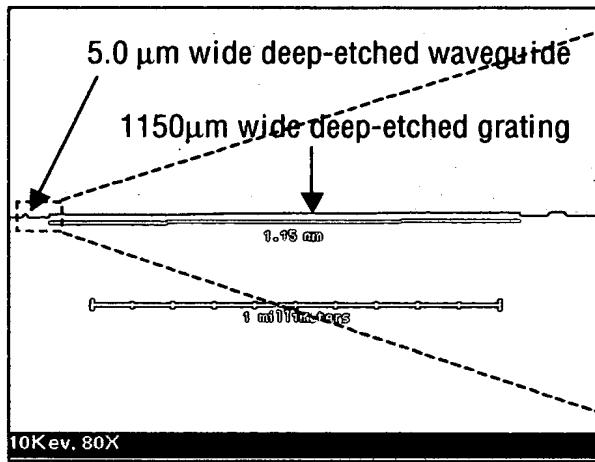


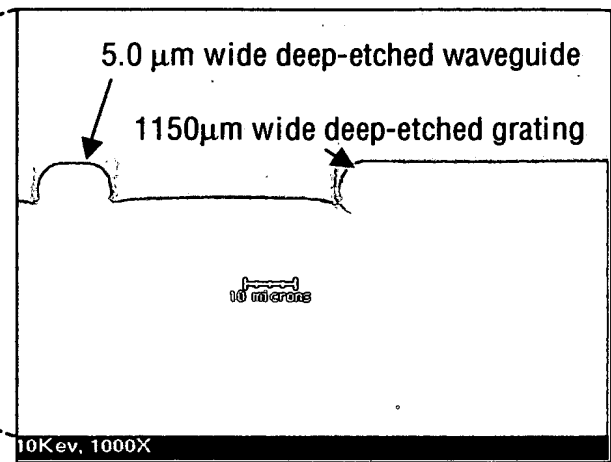
FIG. 12



S/N 09/956,916
A/U 1762

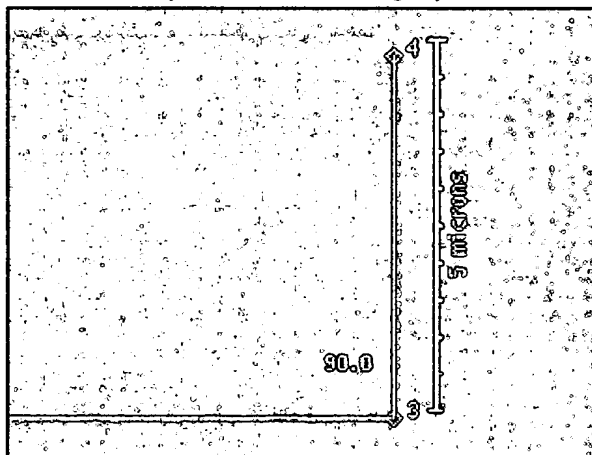


(a)



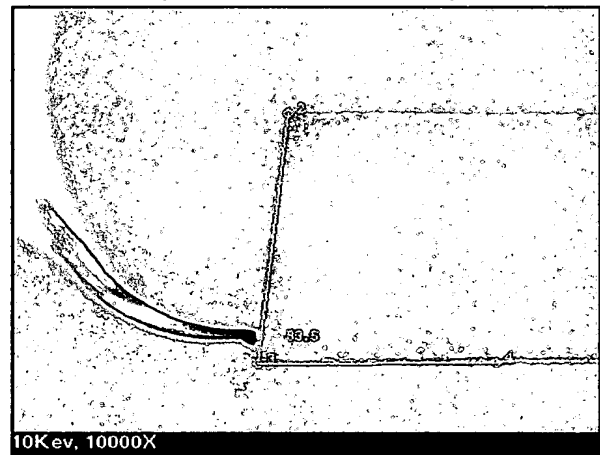
(b)

5.0 μm wide deep-etched waveguide
(90° side-wall angle)



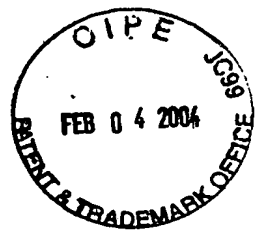
(c)

1150 μm wide deep-etched grating
(83.6° side-wall angle)



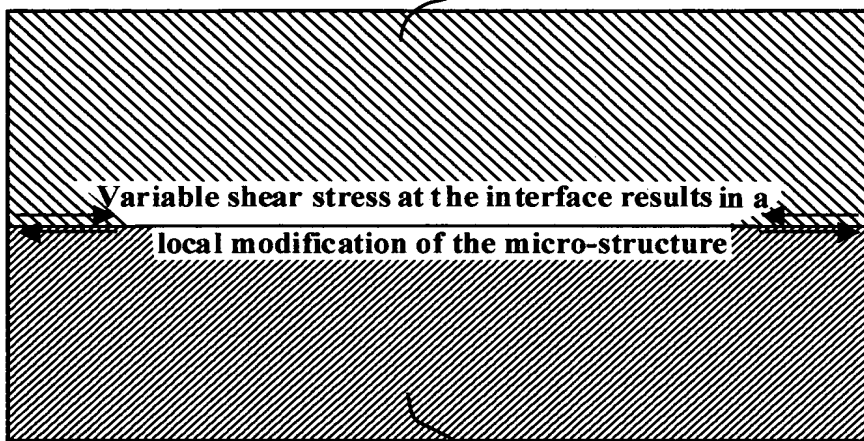
(d)

FIG. 13



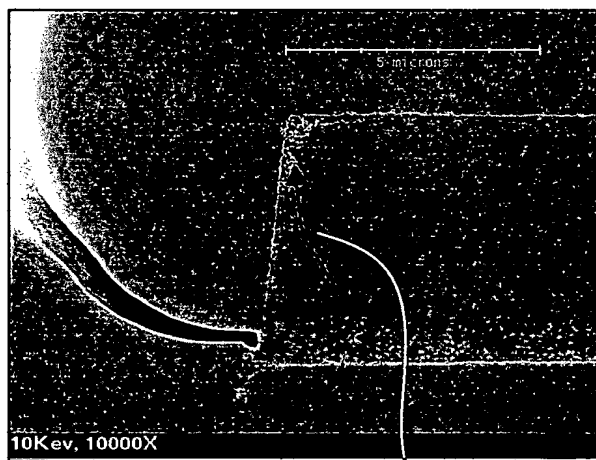
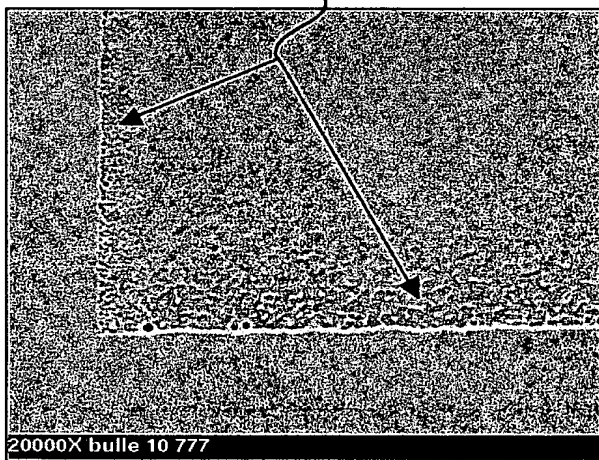
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**Tensile stress Core
(Core wants to contract)**



**Compressive stress Buffer (Clad) layer
(Buffer (Clad) layer wants to expand)**

**Modified micro-structure
near the interfaces**

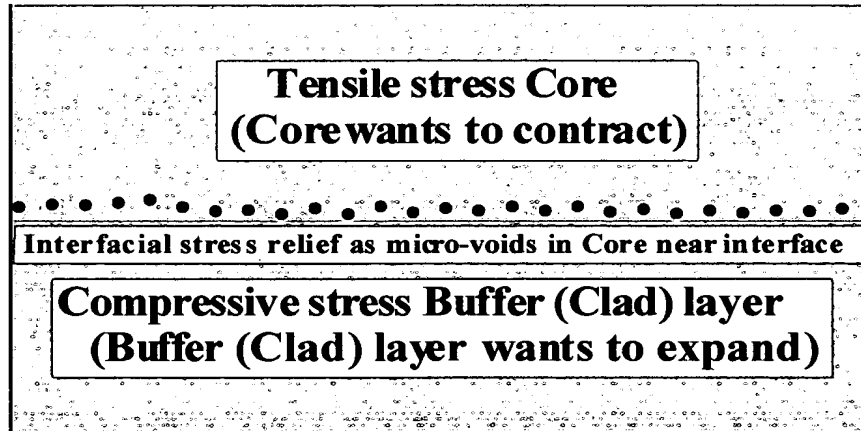


**Modified micro-structure
near the interface**

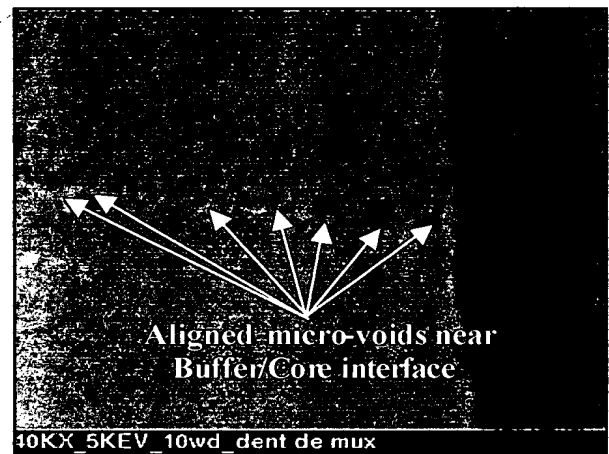
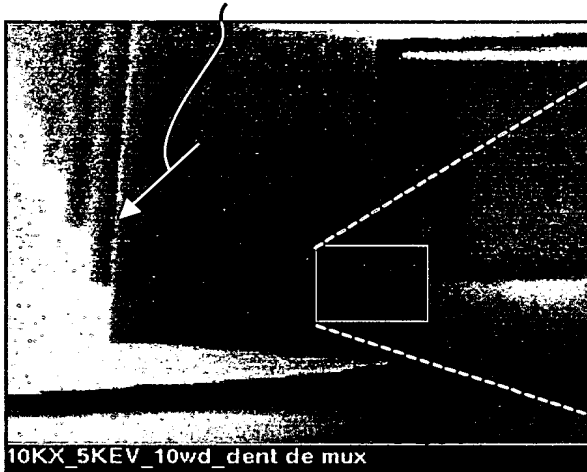
FIG. 14



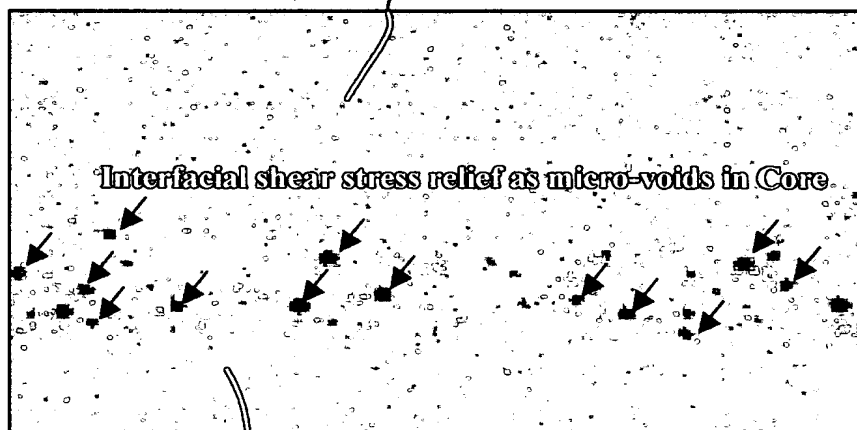
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Sloped side-wall
deep-etched grating



Tensile stress Core
(Core wants to contract)



Compressive stress Buffer (Clad)
(Buffer (Clad) wants to expand)

FIG. 15



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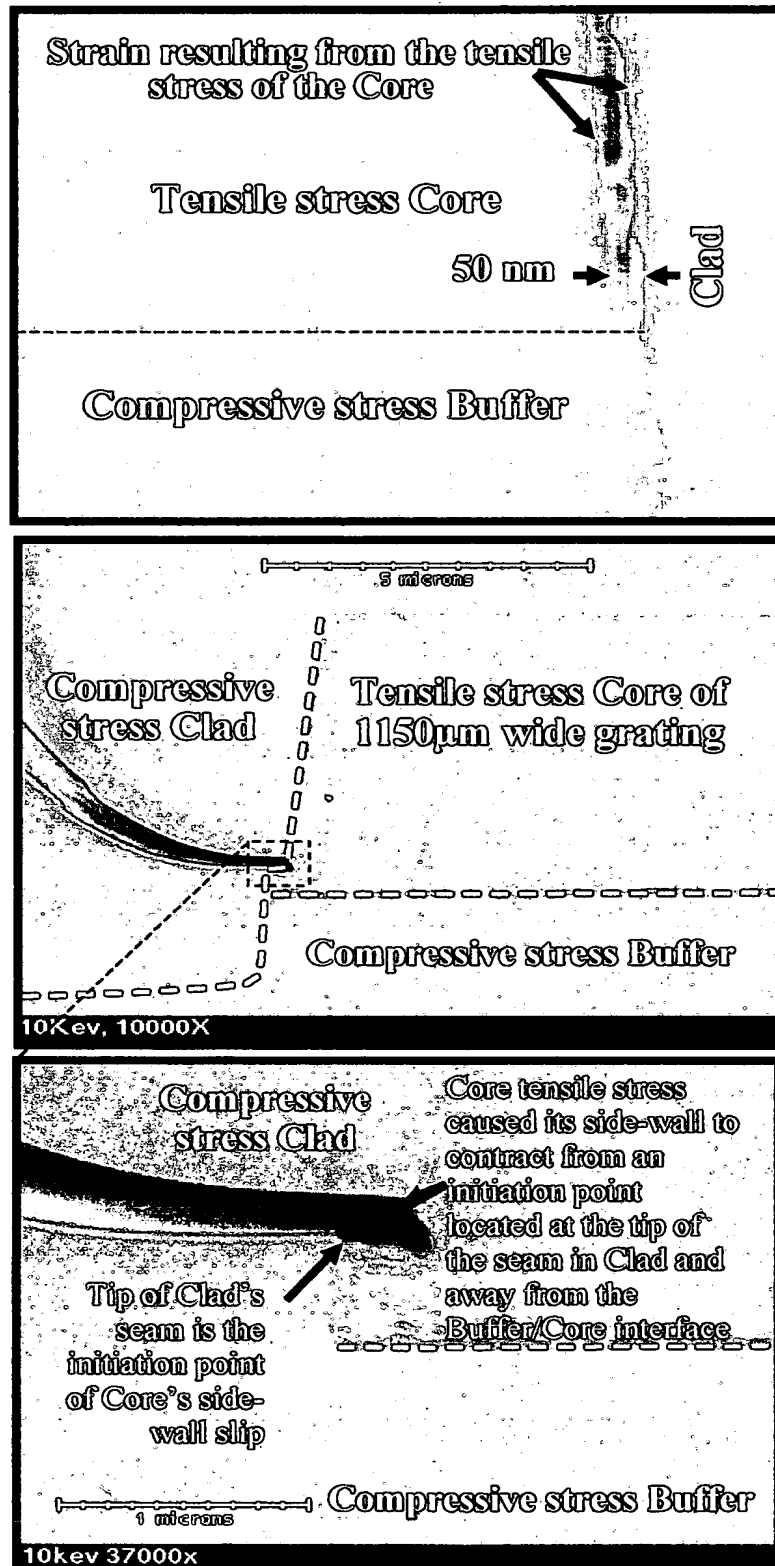
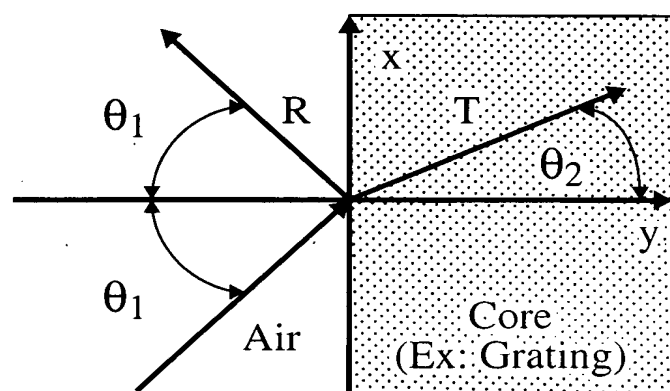


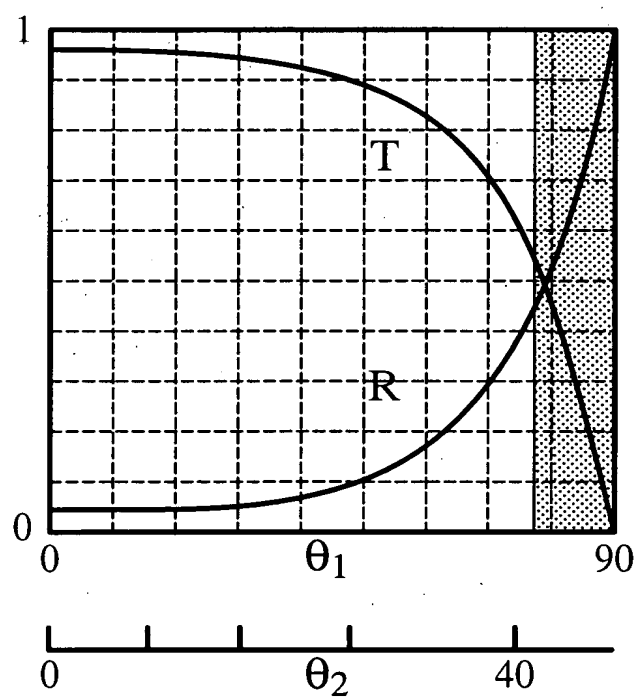
FIG. 16



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A/u 1762



Electric Field \perp Plane of Incidence



Electric Field \parallel Plane of Incidence

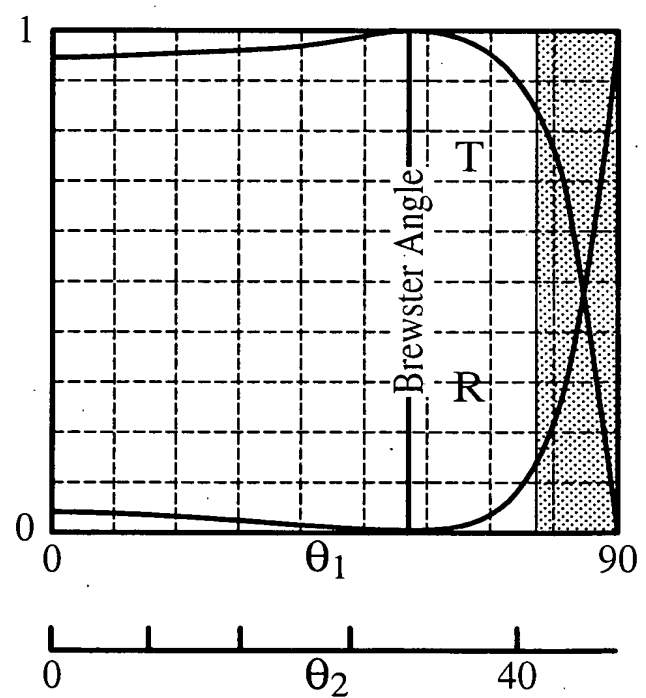
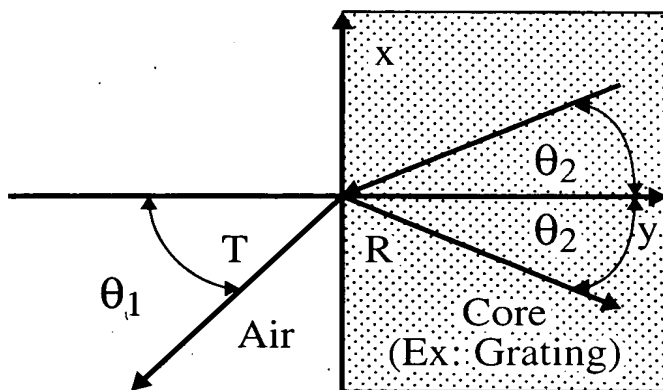


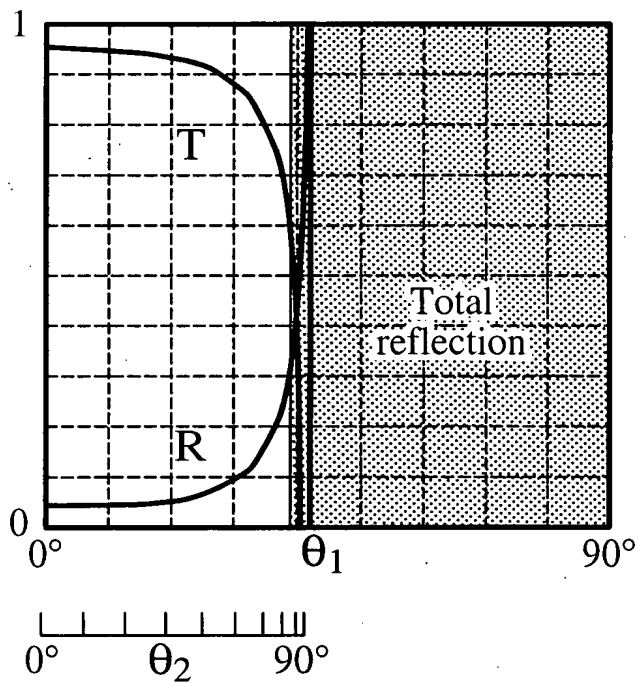
FIG. 17



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Electric Field \perp Plane of Incidence



Electric Field \parallel Plane of Incidence

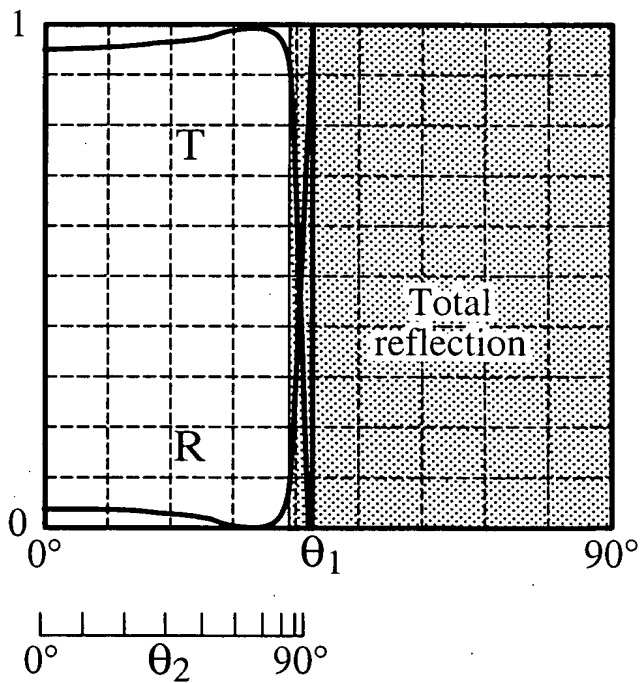


FIG. 18